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**Industrial
Summit**
GOES ON TOUR 2023
Powering Your Sustainable Innovation



Digital Power Approach with STM32G4 in 3kW 5G Telecom Rectifier

Industrial Power & Energy Competence Center
Asia Pacific

Max Yi

Power & Energy
Competence
Center



Agenda

1 Background

4 ST Products introduction

2 Introduction for 3kW Digital Solution

5 Summary

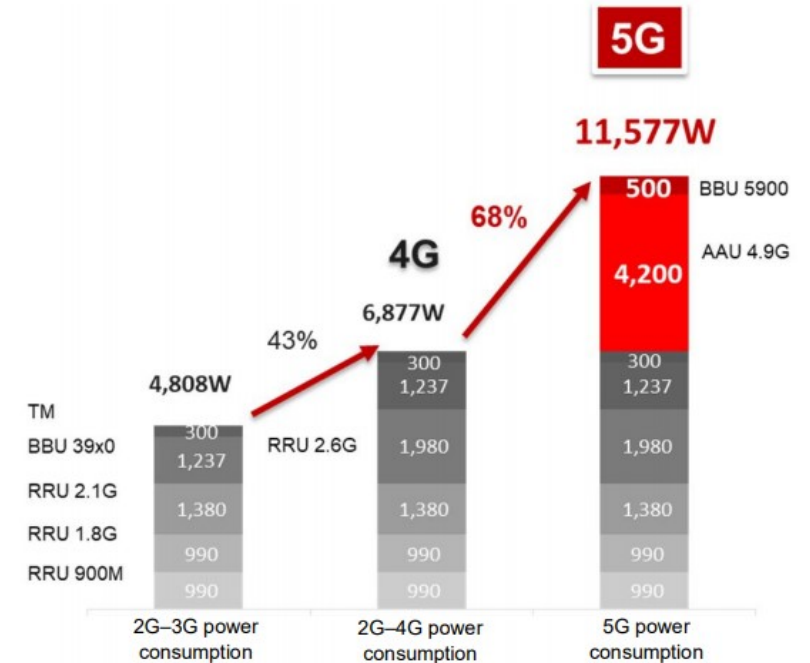
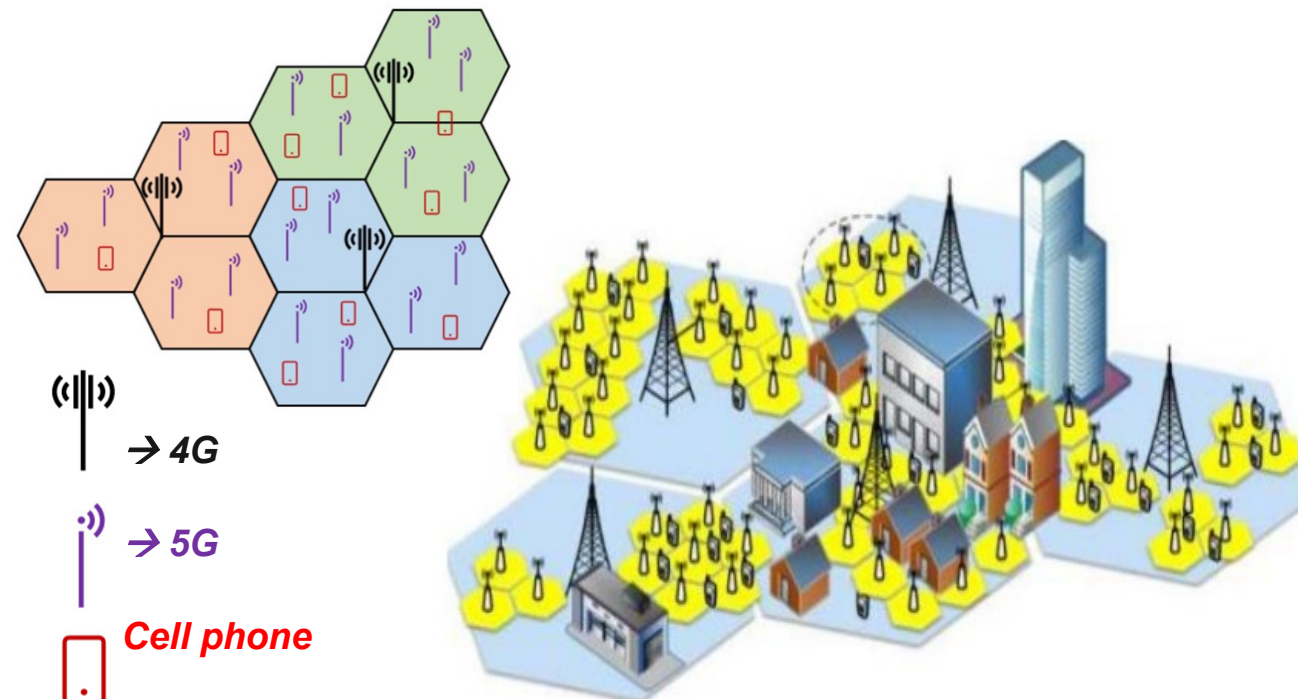
3 EVM Board Performance

Background

5G Telecom power requirements

Higher system integration is the Key for 5G power
Provides higher power density and higher efficiency!

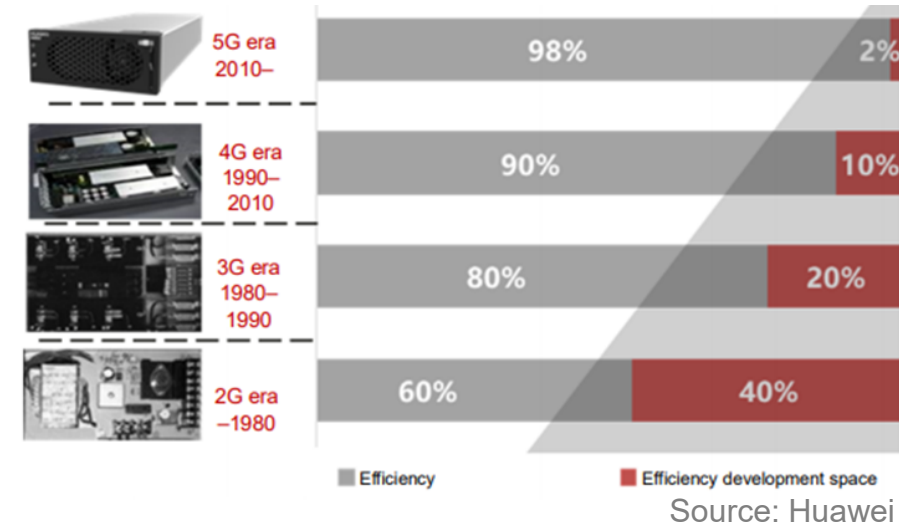
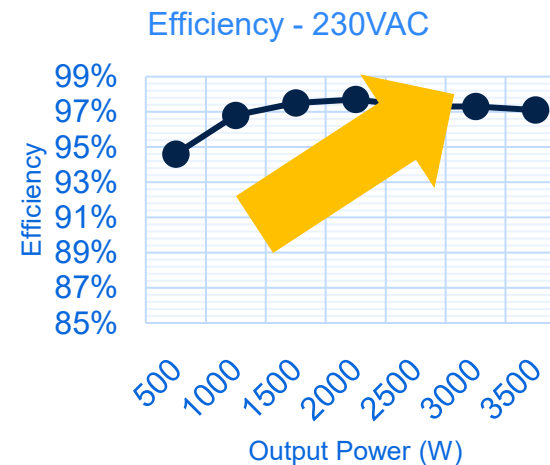
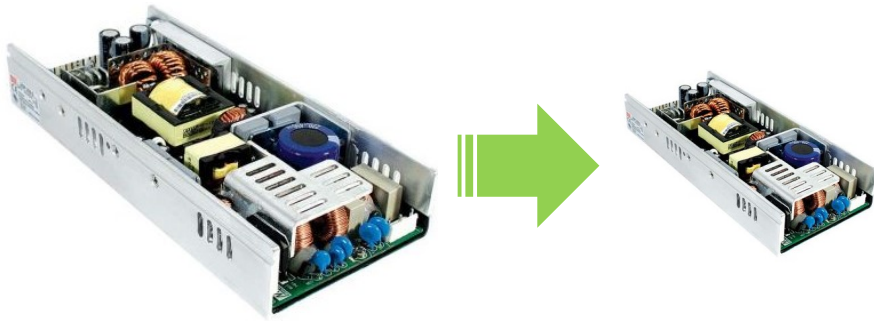
- **Smaller coverage due to higher frequency radio:** in order to achieve high network speed and low latency
- **Higher power consumption in 5G usage:** in order to fulfill high traffic density and connection density



Digital solution for 5G power applications

To achieve high system integration, we need..

- High flexibility and good adaptability for advanced topologies to achieve high efficiency
- Provide benefit on downsizing and BOM reduction
- Support communication for real-time monitoring (safety)
- Less component variation (high reliability)



Introduction for 3kW Digital Solution



Telecom Rectifier/Datacenter/Server

Prototype: Q2/21
Final Release: Q4/21

3kW CCM TTP PFC + FB LLC + SR -Telecom Rectifier

PE.SP_0001.20



Physical Sample



ST
3kW Telecom
Rectifier

Commercial
2.9kW
Telecom
Rectifier

Application key features:

- Fully Digital AC-DC Power Supply
- Input AC Voltage: 90 VAC up to 264 VAC
- Input AC Frequency: 47Hz to 63Hz
- DC output voltage: 53.5 VDC
- Peak Efficiency > 96.5% @ 230VAC
- Power Factor > 0.99 @ 100% load
- iTHD < 5% @ 100% load
- Hold up time: 10ms
- Outline Dimension: 100mm*310mm*41mm
- Power Density up to 40W/inch³
- Peak inrush current < 30A

Key Products

PFC: SCTW35N65G2V (SiC MOSFET), STY139N65M5 (SJ MOSFET), STGAP2D (Galvanic insulated gate driver), STM32G4 (32-bit MCU)

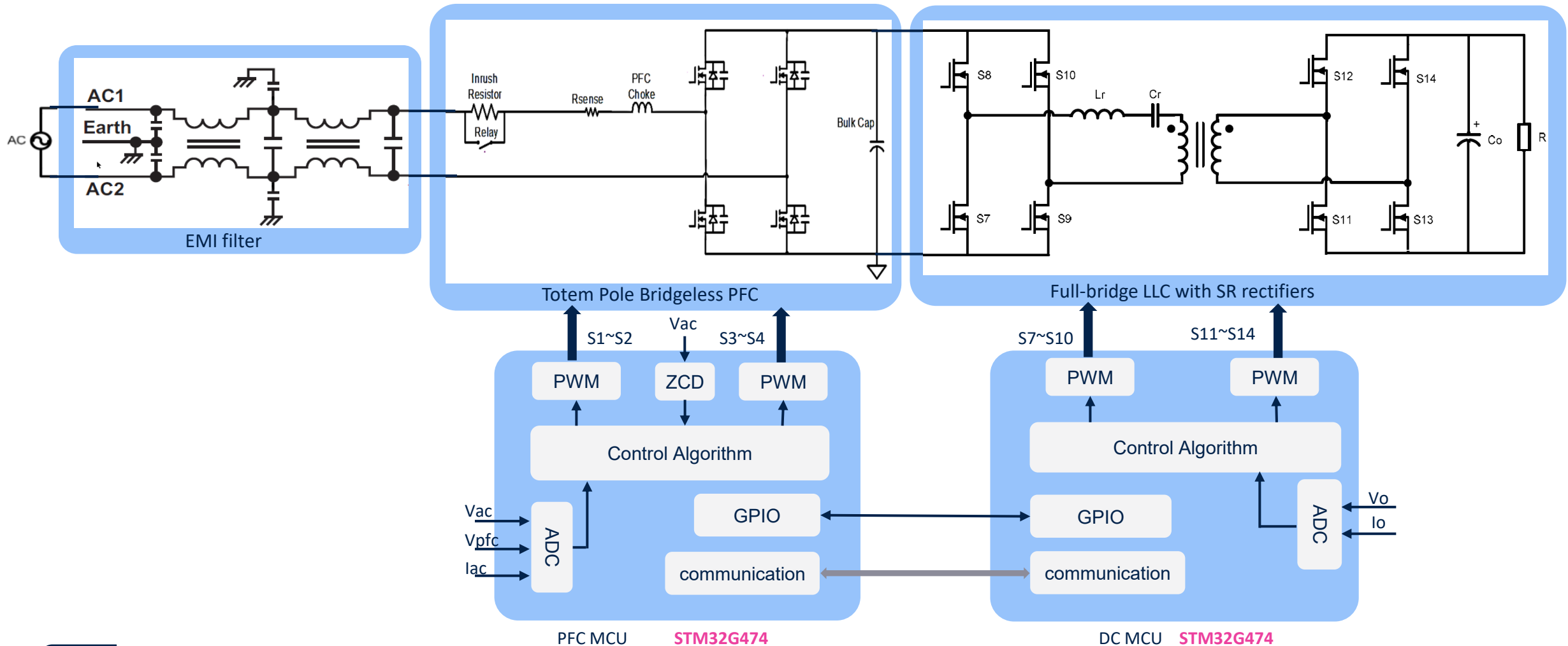
LLC: STW70N65DM6 (SJ MOSFET), STGAP2HS (Galvanic insulated gate driver), STL130N8F7 (SR MOSFET), STDRIVE200H (SR Driver IC), STM32G4 (32-bit MCU)

Aux. Power: VIPer26HD/VIPer38LD (Converter for aux. PS)

Key Benefits

- Peak Efficiency > 96.5%
- Power Density up to 40W/inch³

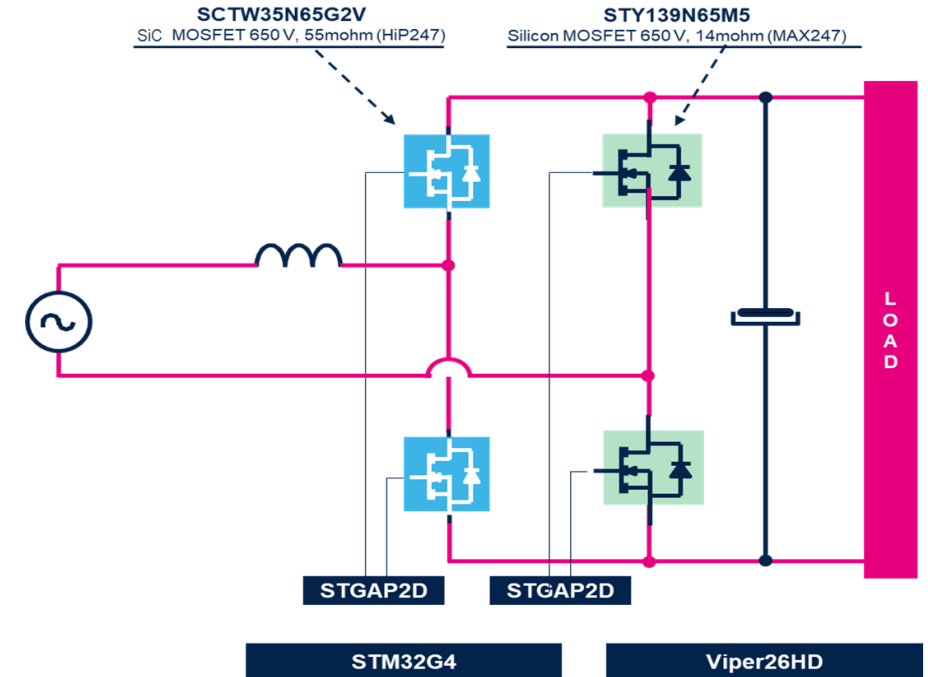
Simplified block diagram



CCM Totem Pole PFC solution Based on SiC MOSFET

Key Specs

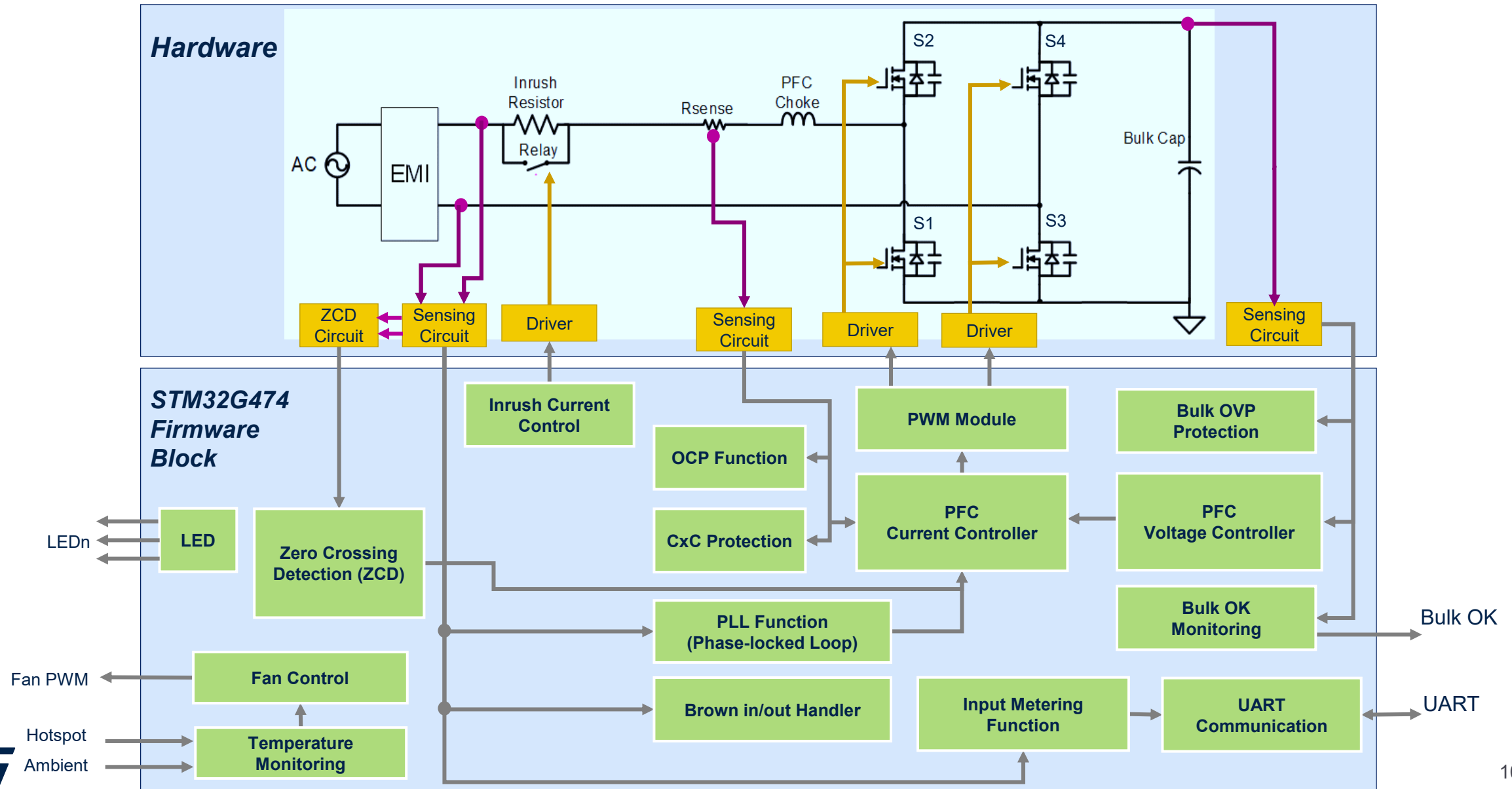
- Input AC voltage: 90VAC up to 264VAC
- Input Inrush Current: < 30A
- Switching Frequency : 70kHz
- Operation Mode: CCM
- Peak Efficiency: 98.5% @ 230VAC
- Power Factor > 0.99 @ 100% load
- iTHD < 5% @ 100% load
- Digital (STM32G4) Power Control



Key Products:

- SCTW35N65G2V (SiC MOSFET)
- STY139N65M5 (SJ MOSFET)
- STGAP2D (Galvanic insulated gate driver)
- STM32G4 (32-bit MCU)

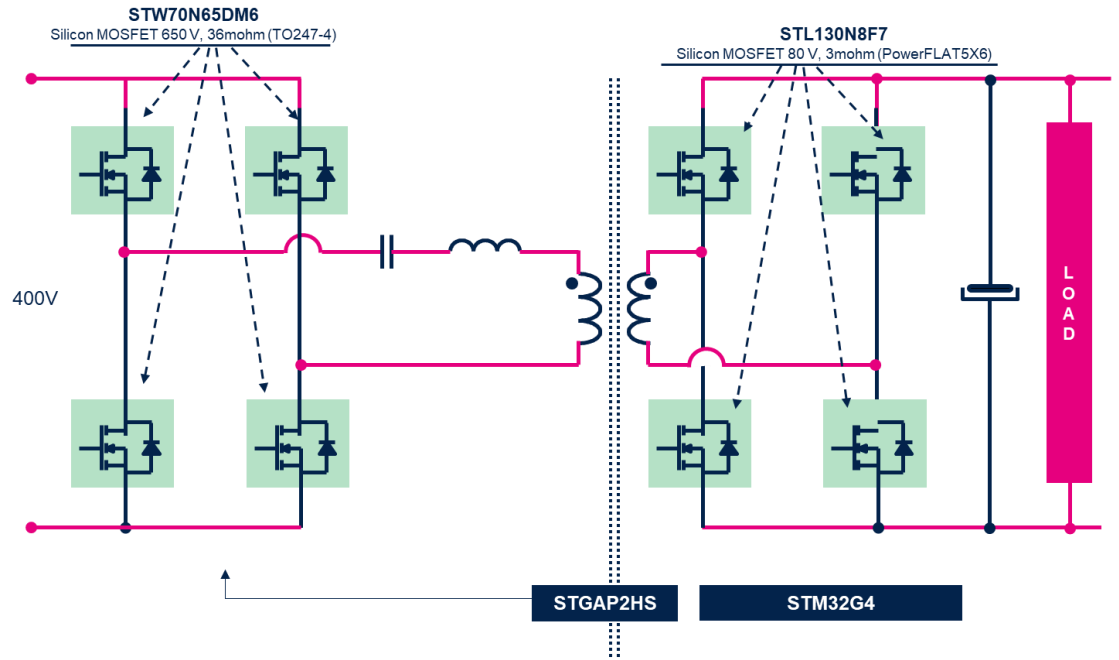
Totem-Pole PFC block diagram



3kW Full-Bridge LLC solution

Key Specs

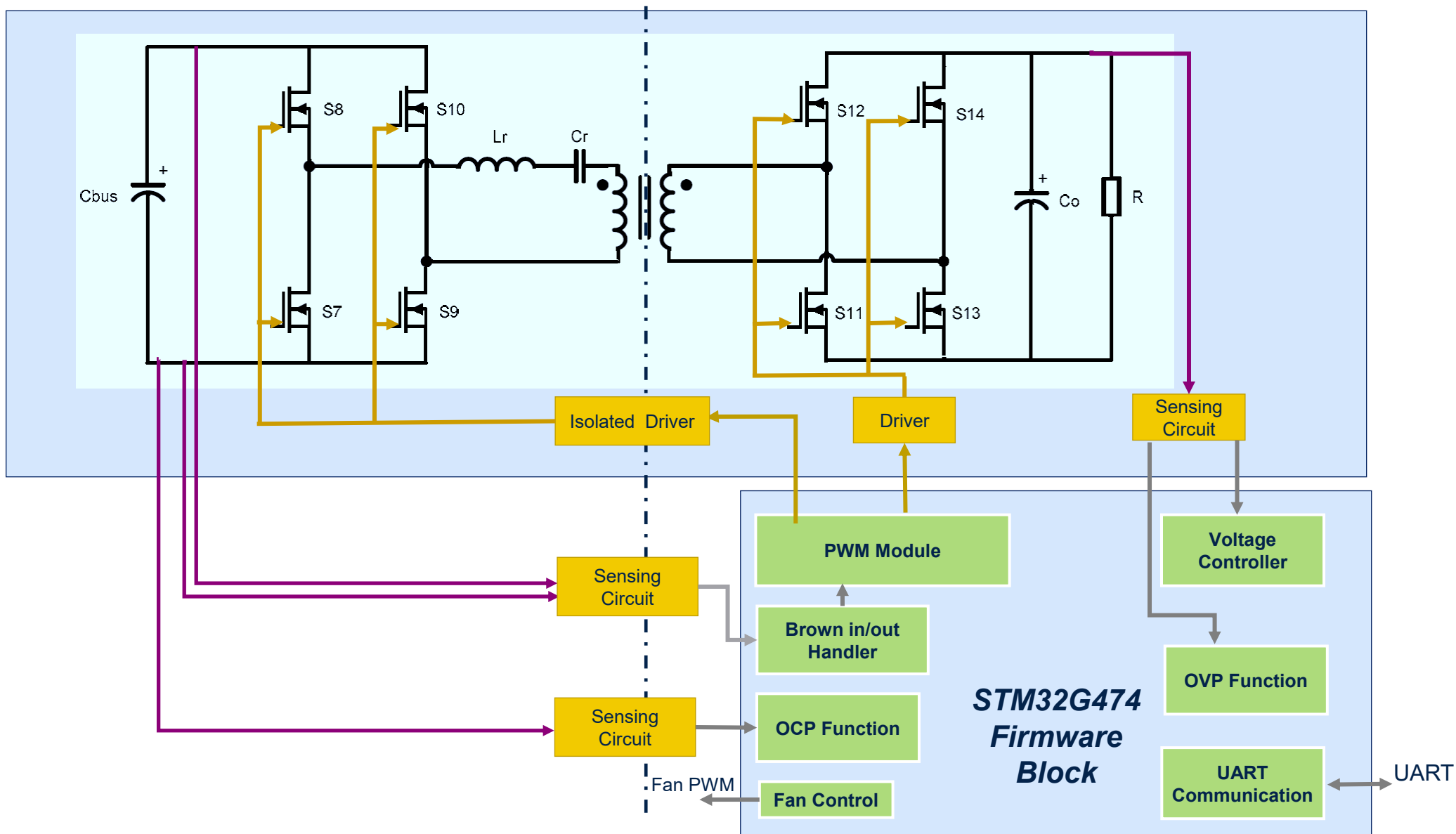
- Input DC voltage: 350V - 425V
- Output Voltage: 53.5V
- Switching Frequency : 80kHz – 150kHz
- Resonant Frequency: 115kHz
- Peak Efficiency: 98.2%
- Output Voltage Dynamic Response: < 5%
- Digital (STM32G4) Power Control



Key Products:

- STW70N65DM6 (HV MOSFET)
- STL130N8F7 (SR MOSFET)
- STGAP2HS (Galvanic insulated gate driver)
- STM32G4 (32-bit MCU)
- VIPer38LD (converter for aux. PS)

FB LLC block diagram

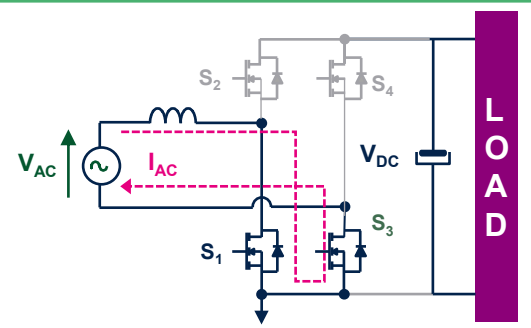


Operation mode for Totem-Pole PFC

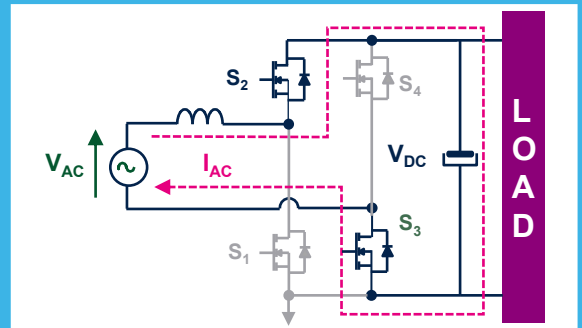
$$V_{AC} > 0$$

S1 controls PFC choke charging
S3 can be switched on to reduce voltage drop of the body diode

S1 on, inductor current rising



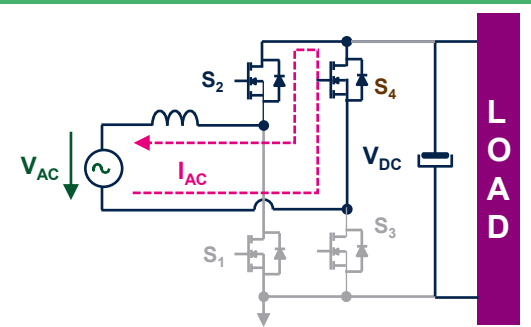
S1 off, inductor current falling



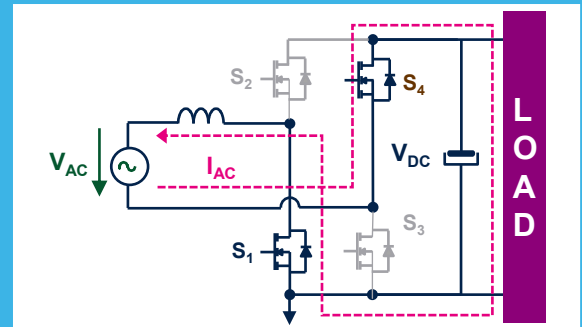
$$V_{AC} < 0$$

S2 controls PFC choke charging
S4 can be switched on to reduce voltage drop of the body diode

S2 on, inductor current rising

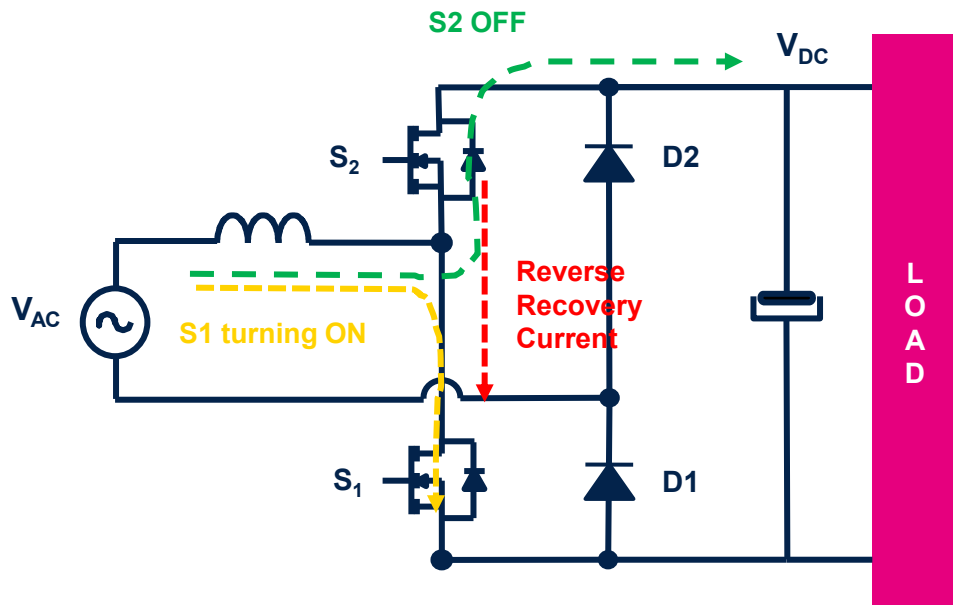


S2 off, inductor current falling

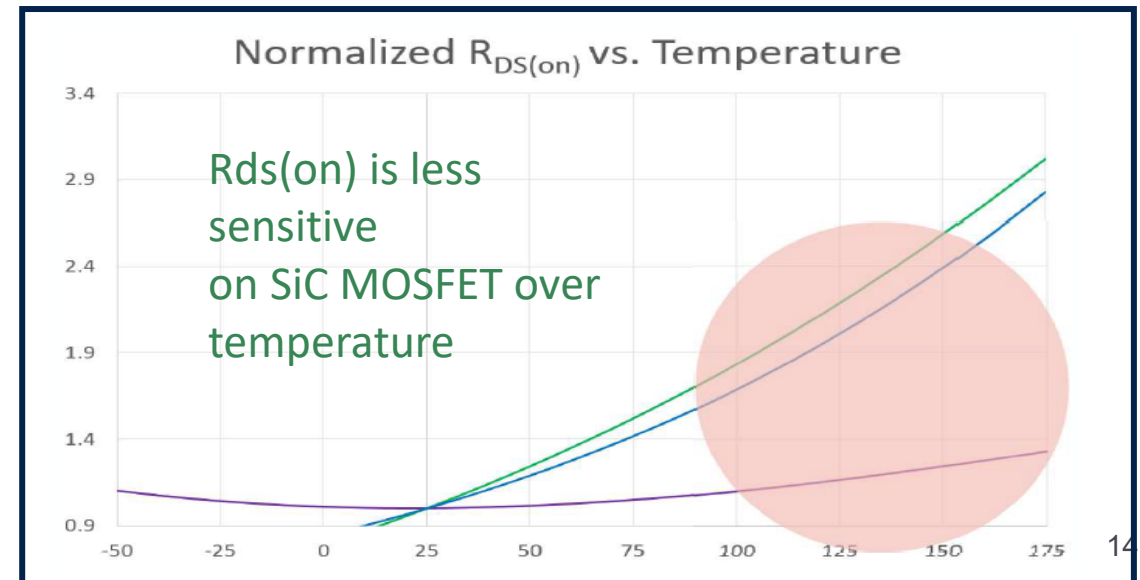
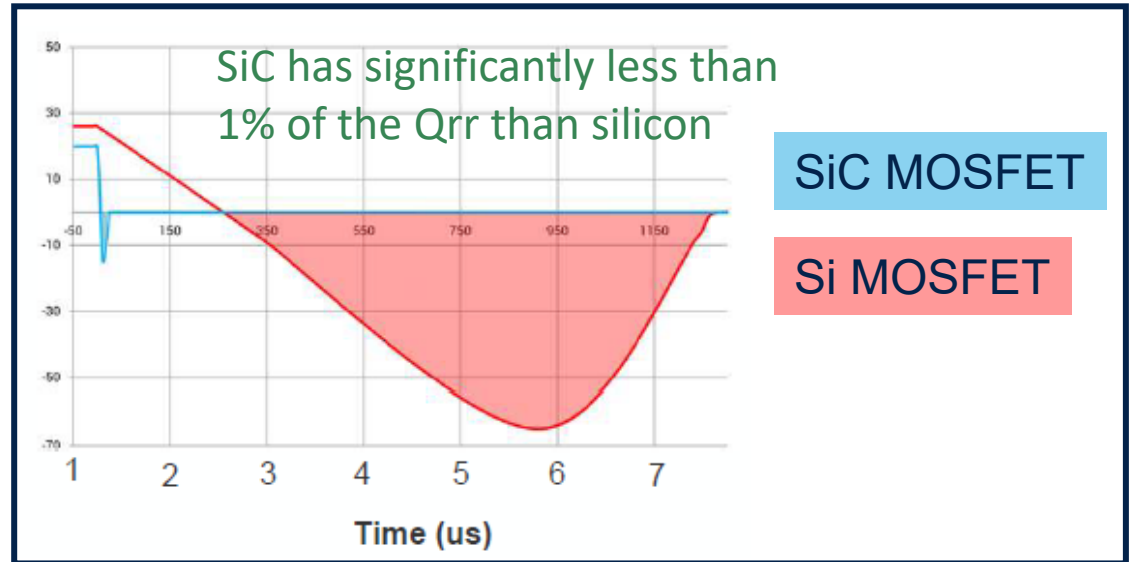


SiC MOSFET and driver IC

650V Gen2 SiC MOSFET



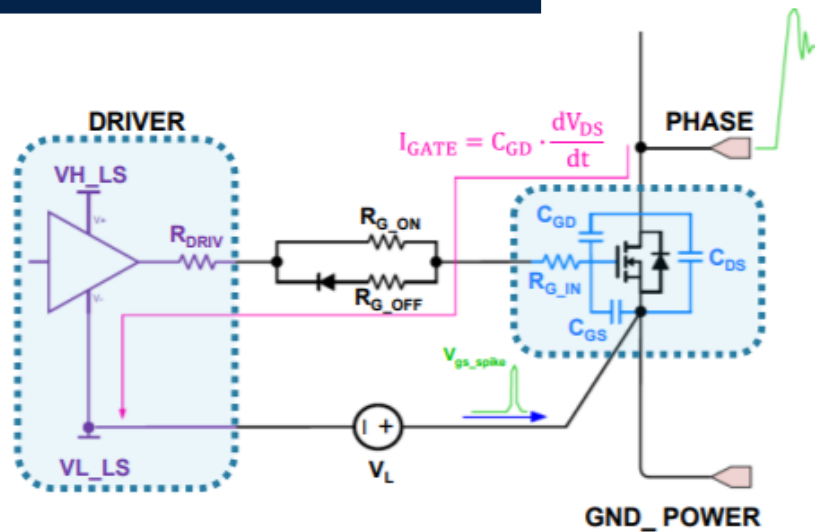
- Low body diode reverse recovery.
- Low switching loss due to outstanding figure of merit
- Low power loss at high temperature due to less temperature dependence of on resistance



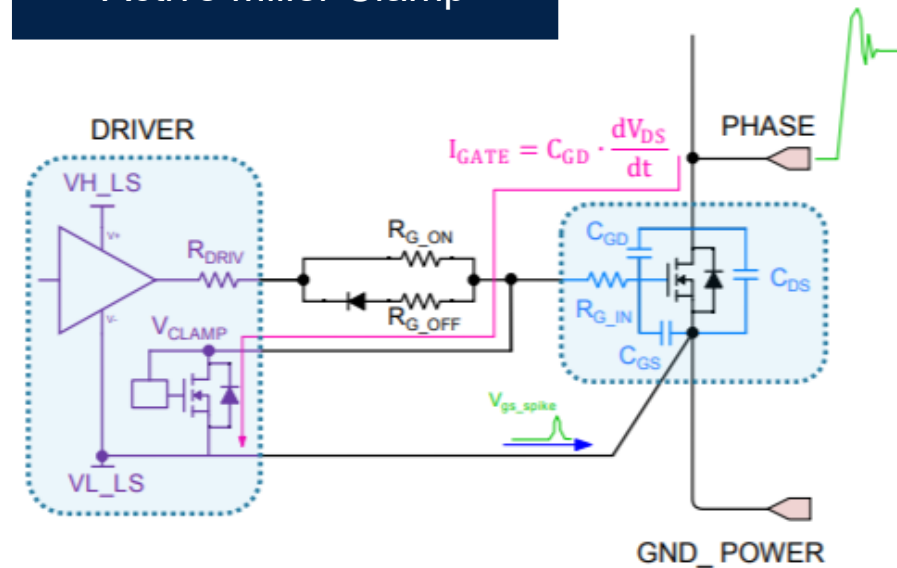
Mitigation techniques for induced G-S glitches

- SiC MOSFET can generate high slew rate dv/dt transients
- High slew rate dv/dt may generate Miller turn-on spike at gate terminal
- Negative turn-off bias also helps to prevent fault trigger due to V_{gs} glitch
- Active miller clamp feature minimizes V_{gs} glitch

Negative gate driving

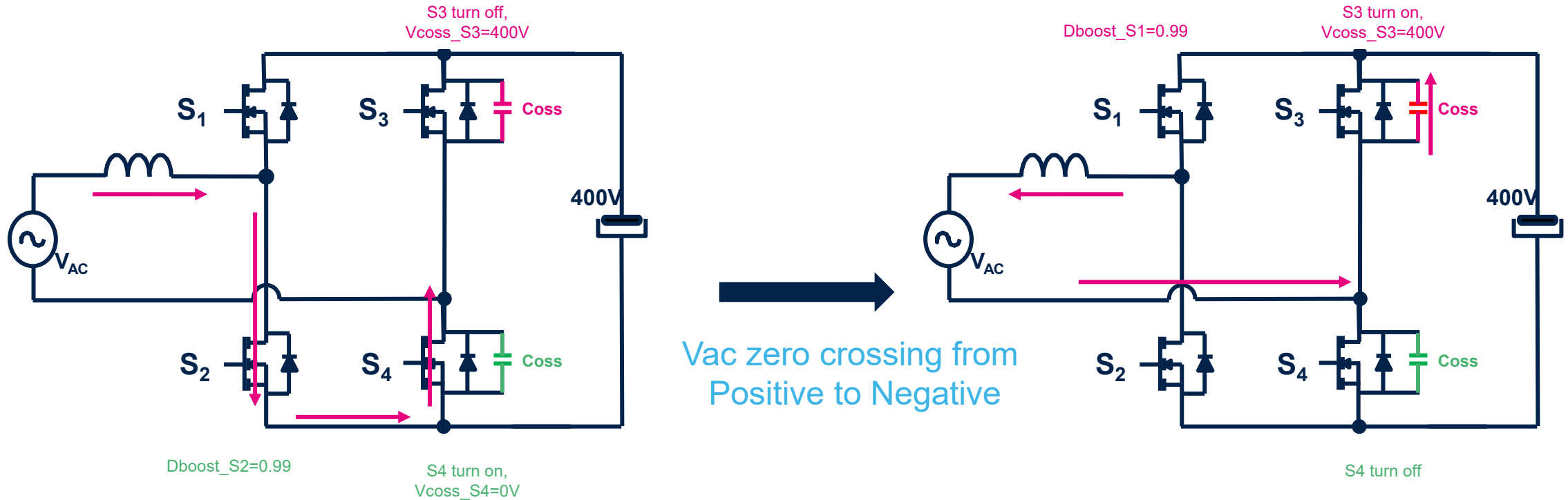


Active Miller Clamp



Design challenge

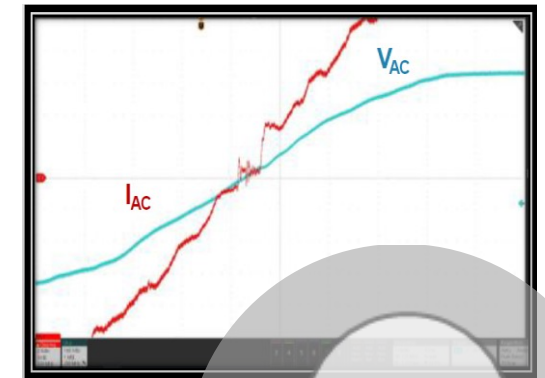
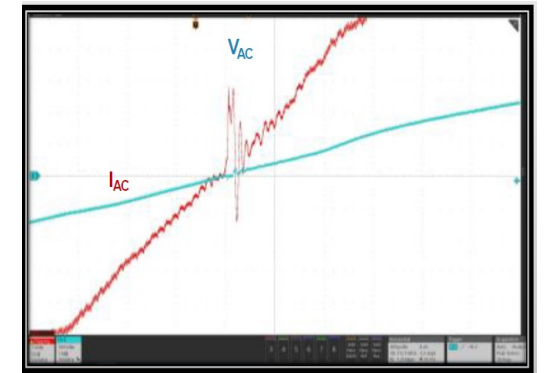
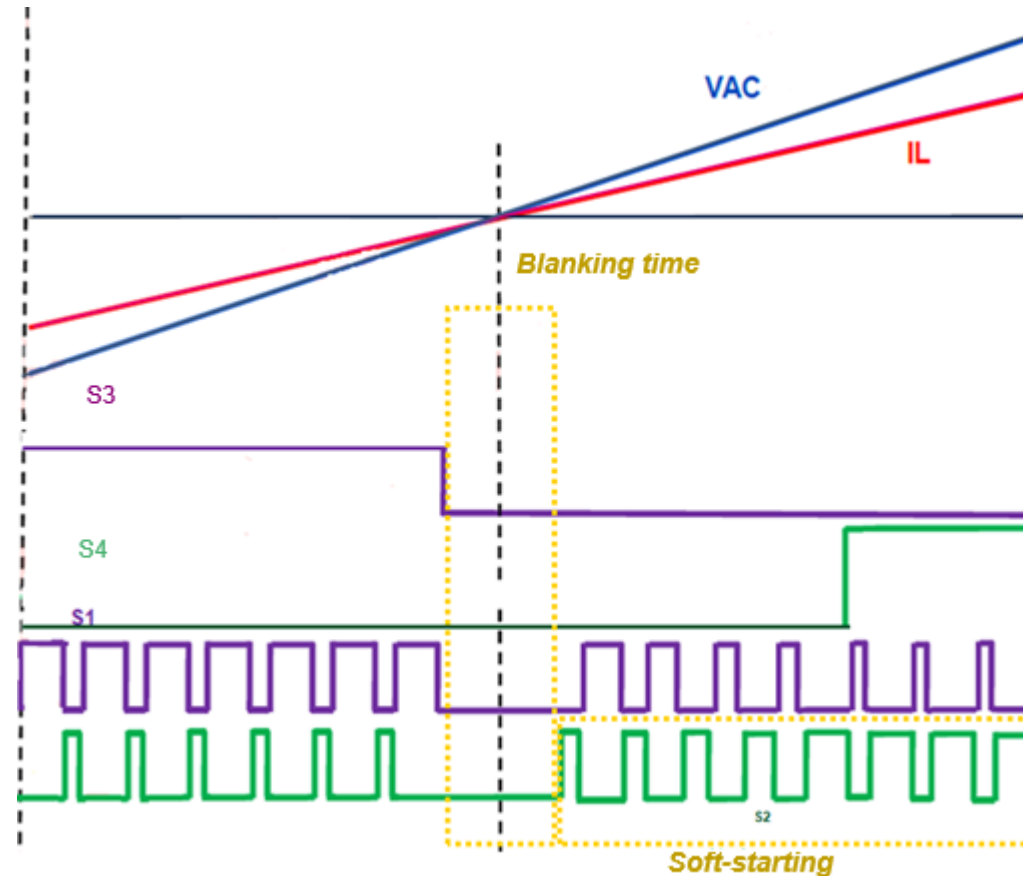
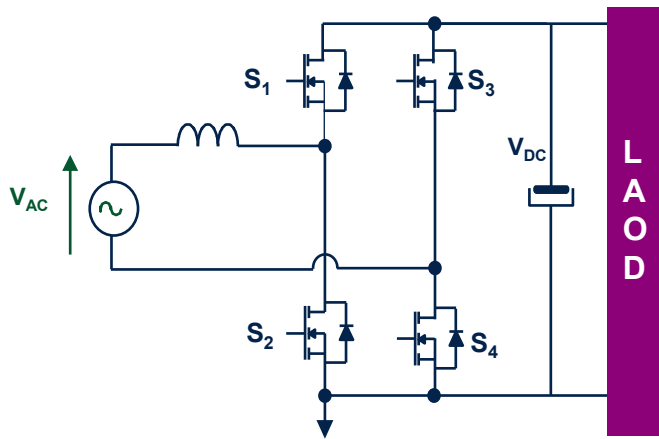
Current spike at AC zero crossing



- At a zero-crossing when the AC input is going from positive to negative.
 - Before zero-crossing, $V_{coss_S3}=400V$, D_{boost}=0.99 to S2, (1-D_{boost})=0.01 to S1
 - After zero-crossing, $V_{coss_S4}=400V$, D_{boost}=0.99 to S1, (1-D_{boost})=0.01 to S2
- Right at zero-crossing, if D_{boost} changes abruptly, the V_{coss_S3} will cause a current spike.

Solution for Eliminating Current Spike

- Blanking + Soft-start duty scheme

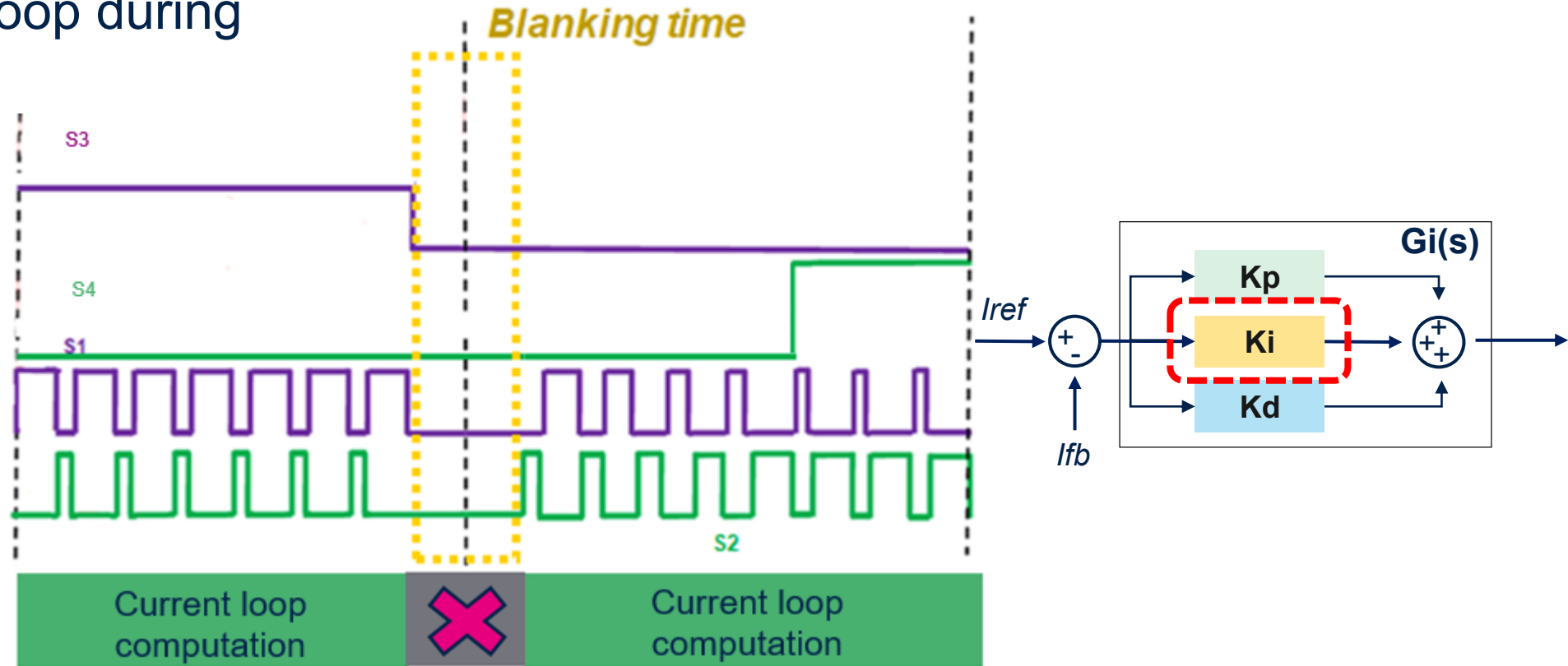


All MOSFETs are turned OFF to ensure a safe permutation of the power switches control and to avoid to short-circuit of the output DC capacitor.

S_1 or S_2 active switches are controlled with a soft duty cycle

Solution for eliminating current spike

- Freeze current loop during blanking time



The control loop should freeze during the blanking time, in order to avoid the integrator of the current loop to generate a large PWM pulse, which will cause a large current spike

Resonant tank design

Magnetizing inductance Lm selection

Considerations:

- Select resonant frequency around 110kHz based power density target
- Main consideration is to achieve the optimal efficiency
- Primary MOSFET Eoff is related to Lm
- Primary MOSFET conducting loss is related to Lm
- Transformer copper loss is related to Lm
- Resonant inductor copper loss is related to Lm
- Power MOSFET ZVS is related to Lm

When operating at $f_s=f_r=116\text{kHz}$, $L_m=225\mu\text{H}$:
 RMS magnetizing current is 2.17A
 MOSFET switching off current is 3.752A
 Voltage/current phase difference is $\Phi=0.309$
 Total zvs discharging capability is 800nC

Calculation

Check maximum Lm to ensure MOSFET ZVS at light load:

$f_{rt} := 150\text{kHz}$

maximun switching frequency at steady status

$C_{oss} := 286 \cdot (1 + 30\%) \text{pF} = 371.8 \cdot \text{pF}$

output capacitor of MOSFET (considering 30% tollerance)

$T_d := 400\text{ns}$

deat time between MOSFETs conduction

$C_{stray} := 100\text{pF}$

parastic capacitor

the peak value of excitation current when $L_m=L_{m_zvs}$, suppose the switching off current of mosfet is peak excitation current, so the current should meet ZVS condition as below:

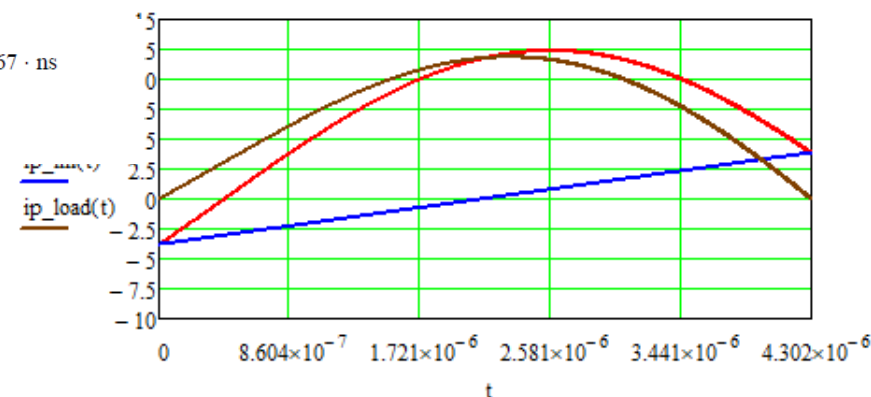
$$I(L_{m_zvs}) := \frac{V_{pfc_v} \cdot \left(\frac{1}{2f_{rt}} - T_d \right)}{4L_{m_zvs}}$$

$L_{m_zvs} := \text{root}[I(L_{m_zvs}) \cdot T_d - (2C_{oss} + C_{stray}) \cdot V_{pfc_t}, L_{m_zvs}, 1\mu\text{H}, 500\mu\text{H}] = 257.892 \cdot \mu\text{H}$

Select $L_m=230\mu\text{H}$, then double check T_d margin at full load:

$$T_{d_max} := \frac{\Phi}{\pi} \cdot \frac{1}{2f_r} = 423.467 \cdot \text{ns}$$

$T_d < T_{d_max}$, ok



Resonant tank design

Resonant tank Cr, Lr selection

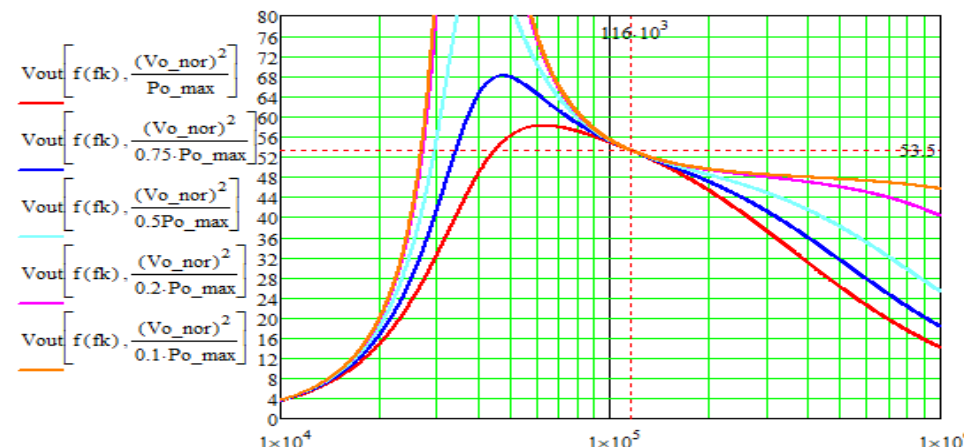
Considerations:

- Influence for efficiency, mainly Lr
- Output voltage range and its corresponding operating frequency range
- Smaller Lr can reduce total resonant inductor power loss
- Smaller Lr will reduce output capability @ low Vin and full load
- Influence for output maintain time during shut down
- Smaller Lr means higher frequency is needed for output regulation @ high Vin and light load

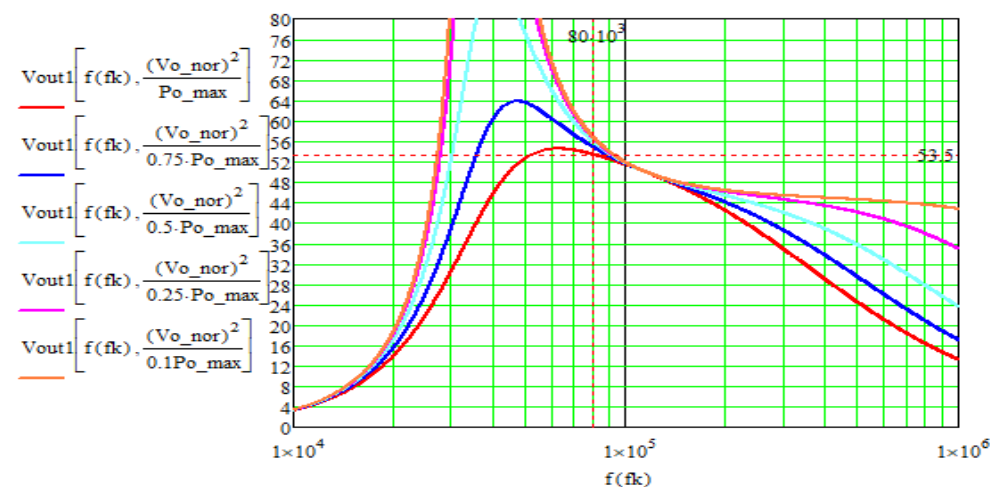
When operating with $L_m=225\mu\text{H}$, $L_r=25\mu\text{H}$, $C_r=75\text{nF}$:
 $K=9$,
 $Q=0.42$ @ full load
 $f_s=80\text{kHz}$ @ $V_{in}=375\text{V}$, $V_{out}=53.5\text{V}$, full load
 $f_s=165\text{kHz}$ @ $V_{in}=425\text{V}$, $V_{out}=53.5\text{V}$, $I_{out}=1\text{A}$

Calculation

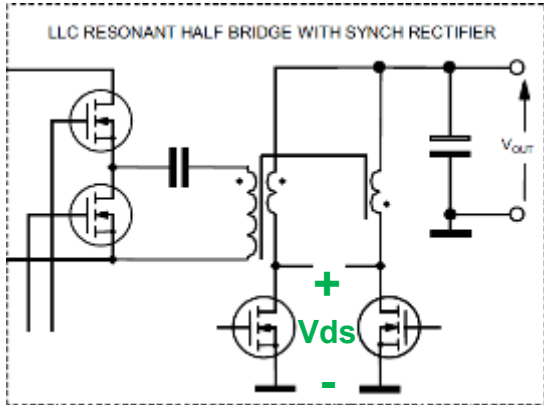
Vout vs. fs @ Vin=400Vdc, each load



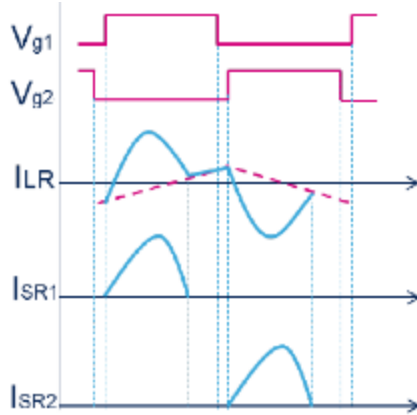
Vout vs. fs @ Vin=375Vdc, each load



Design challenge: Synchronous rectifier (SR) control

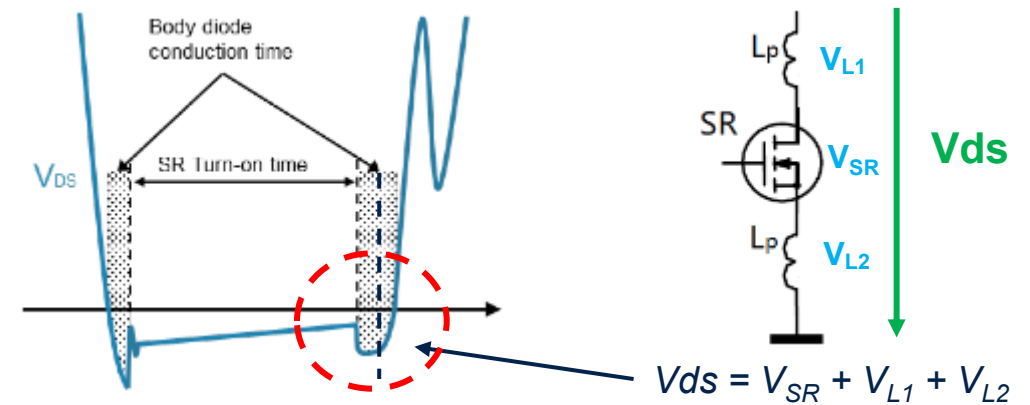


- Negative current caused by late SR MOSFET turn-off



- At heavy load (below resonant frequency), late SR turn off will force MOSFET conduct and cause a negative current from output capacitor
- This negative current could damage the power MOSFETs and resulting unit failure

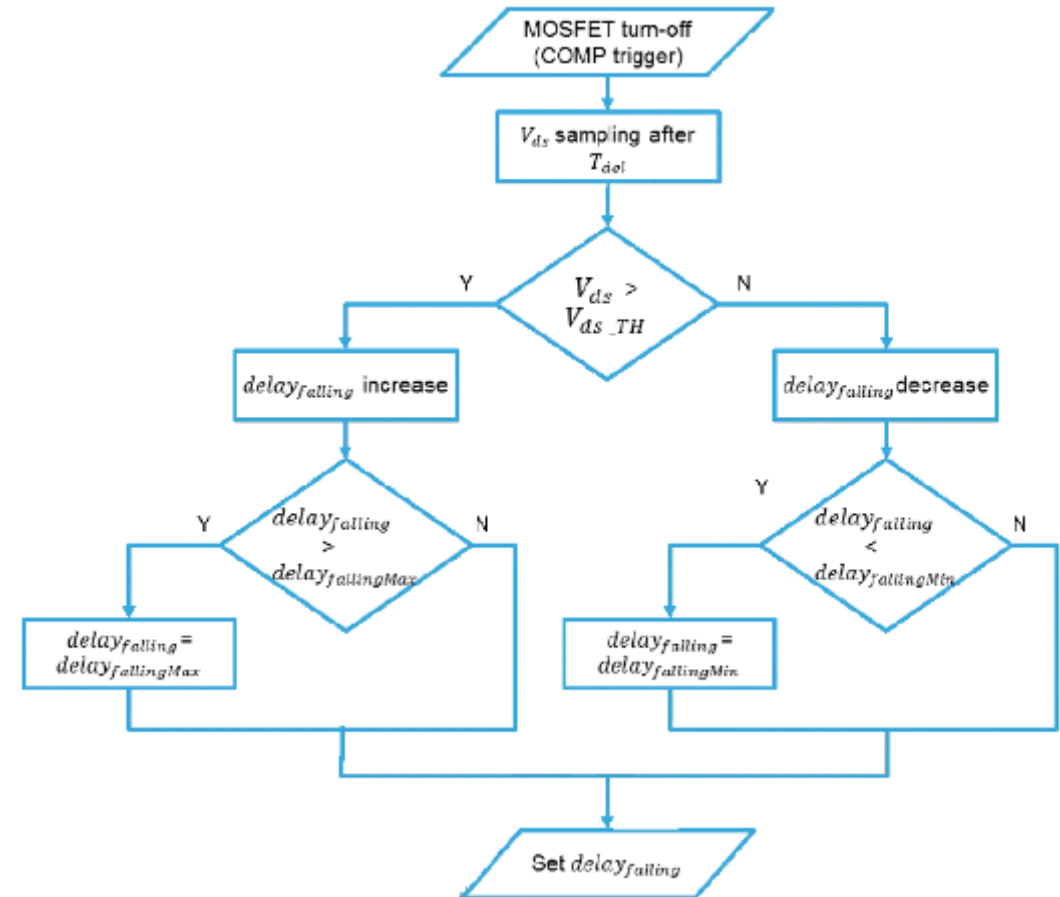
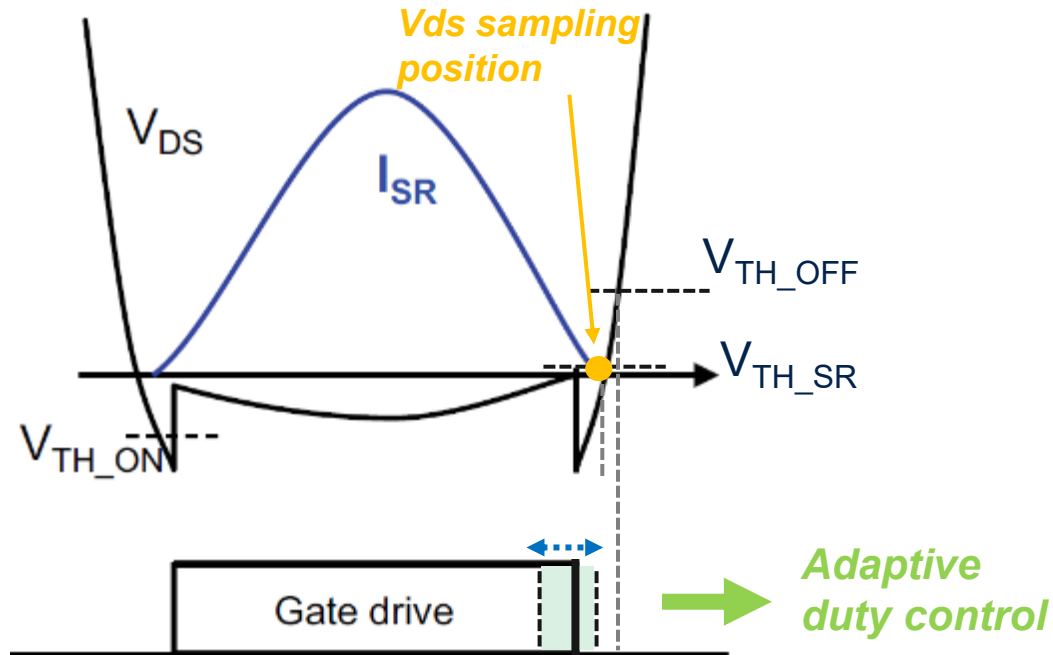
- Premature SR MOSFET turn-off



- Due to the stray inductance in series with the SR MOSFET, the sensed drain-source signal (V_{ds}) is not really the voltage drop across the SR MOSFET (V_{SR})
- So it will prematurely turn-off SR MOSFET and cause low efficiency

Adaptive SR control solution

- Adaptive SR control algorithm
 - Adaptive duty change for turn-off control bases on the comparison of sampled V_{ds} and V_{TH_SR} threshold



EVM Board Performance

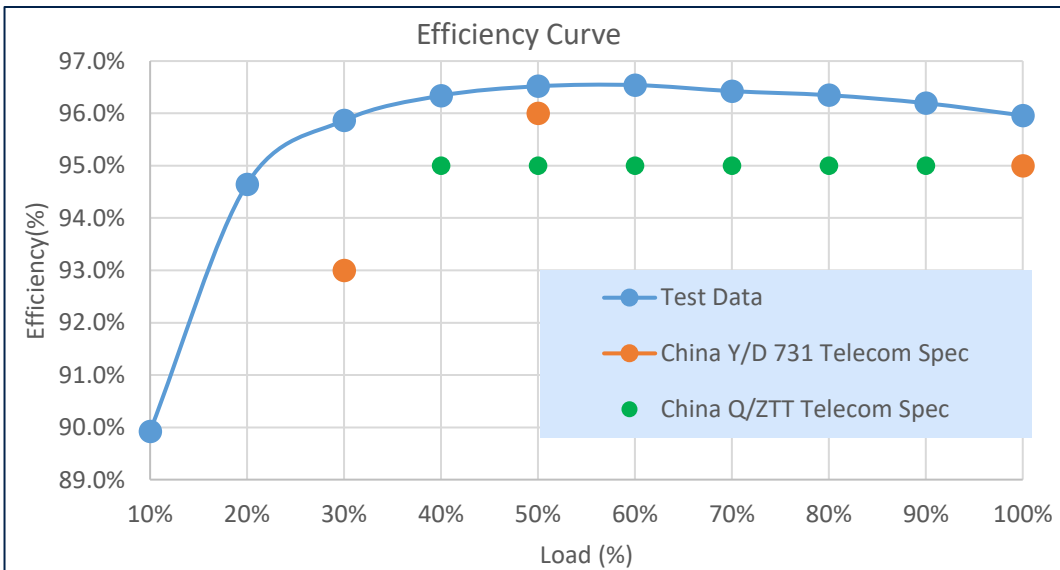
- Efficiency / iTHD / PF
- Soft start up
- Load Transient Response
- Load on with full power
- Hold-up time

Find more information from <https://www.st.com/en/evaluation-tools/stdes-3kwtlcp.html>

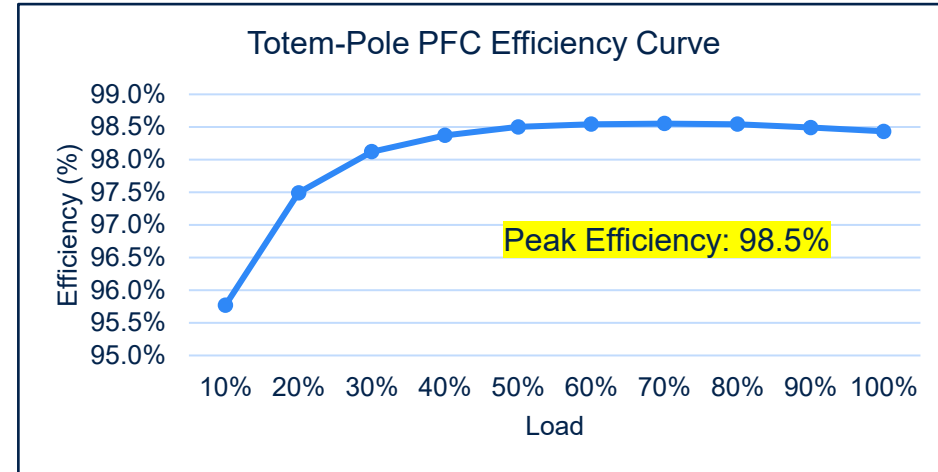
Efficiency curve

Efficiency

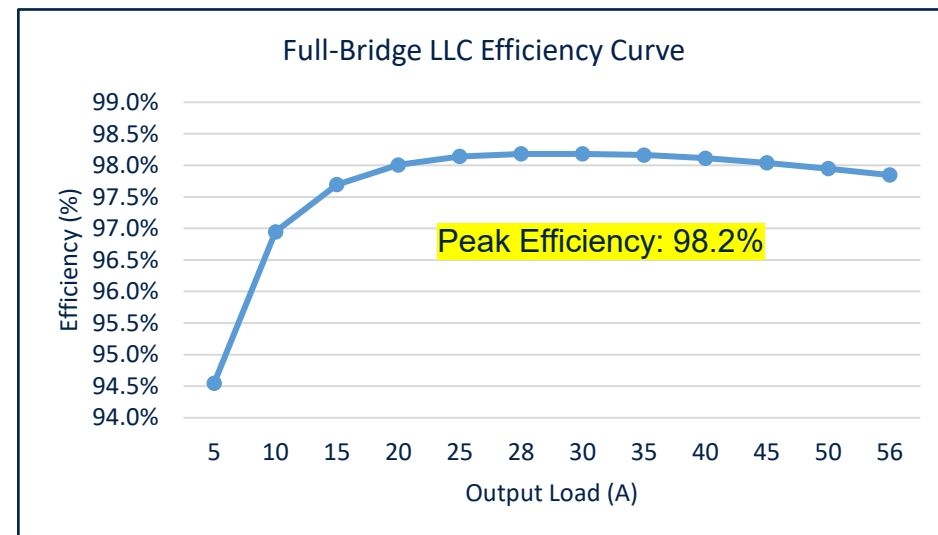
load	Vin	Iin	Pin	Vo	Io	Efficiency
10%	230.65	1.5053	334.4	53.611	5.609	89.92%
20%	230.63	2.7967	634.5	53.576	11.209	94.65%
30%	230.59	4.101	939.4	53.544	16.819	95.87%
40%	230.49	5.423	1245.9	53.515	22.429	96.34%
50%	230.37	6.748	1551.6	53.487	27.999	96.52%
60%	230.32	8.095	1862	53.438	33.639	96.54%
70%	230.21	9.446	2174.2	53.415	39.249	96.43%
80%	230.23	10.806	2485.8	53.39	44.859	96.35%
90%	230.13	12.178	2800	53.369	50.469	96.20%
100%	230.07	13.54	3113	53.345	55.999	95.96%



Totem-Pole PFC Efficiency

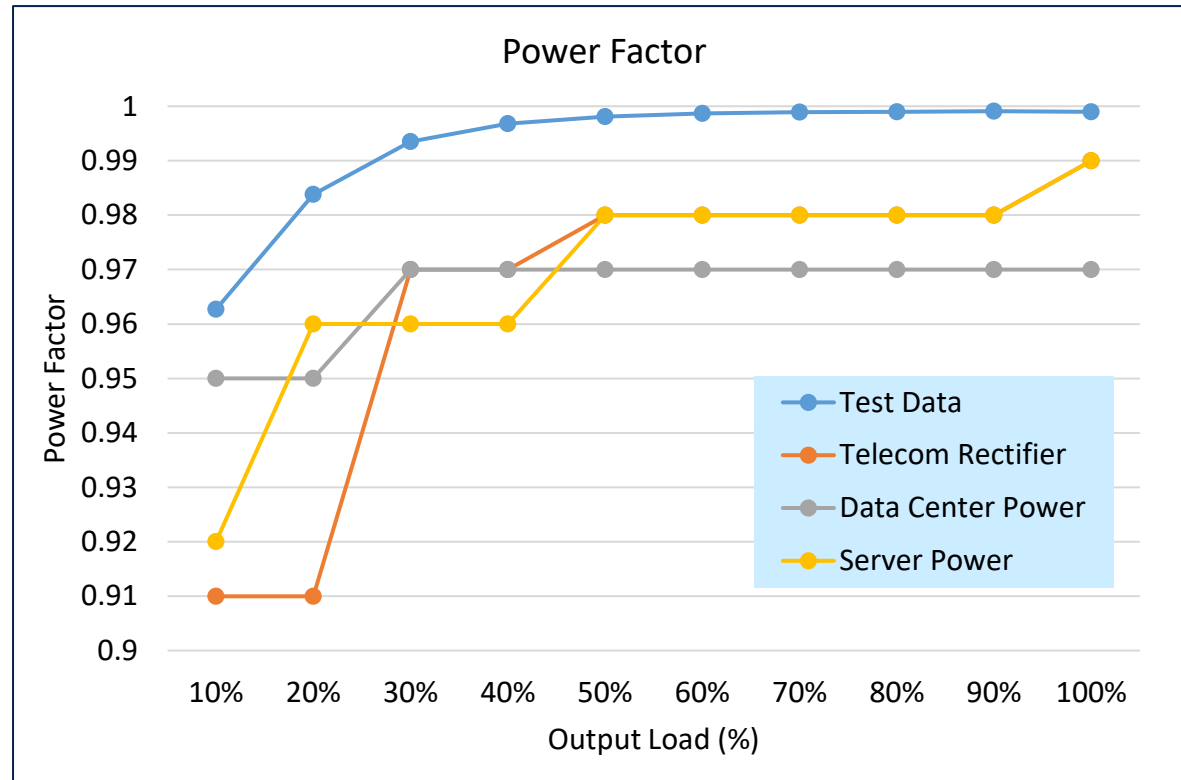


Full-Bridge LLC Efficiency

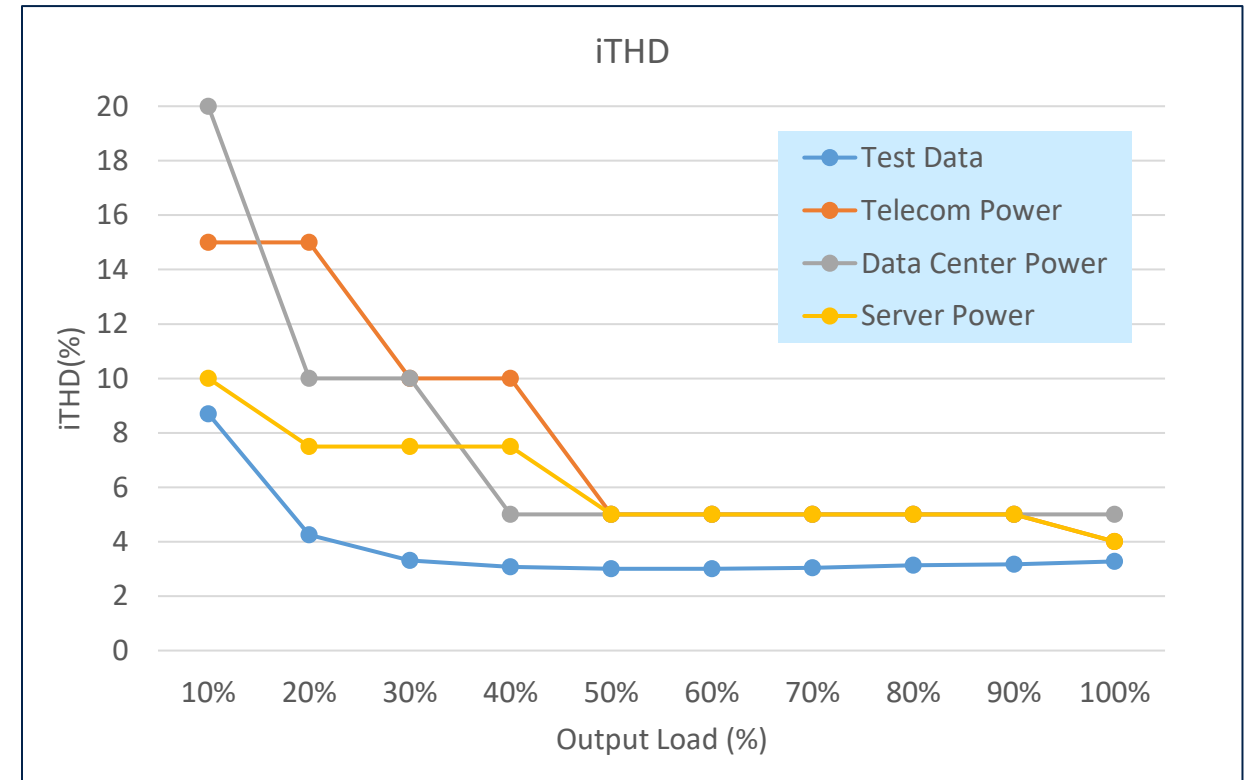


iTHD / Power factor @ 230Vac

PF



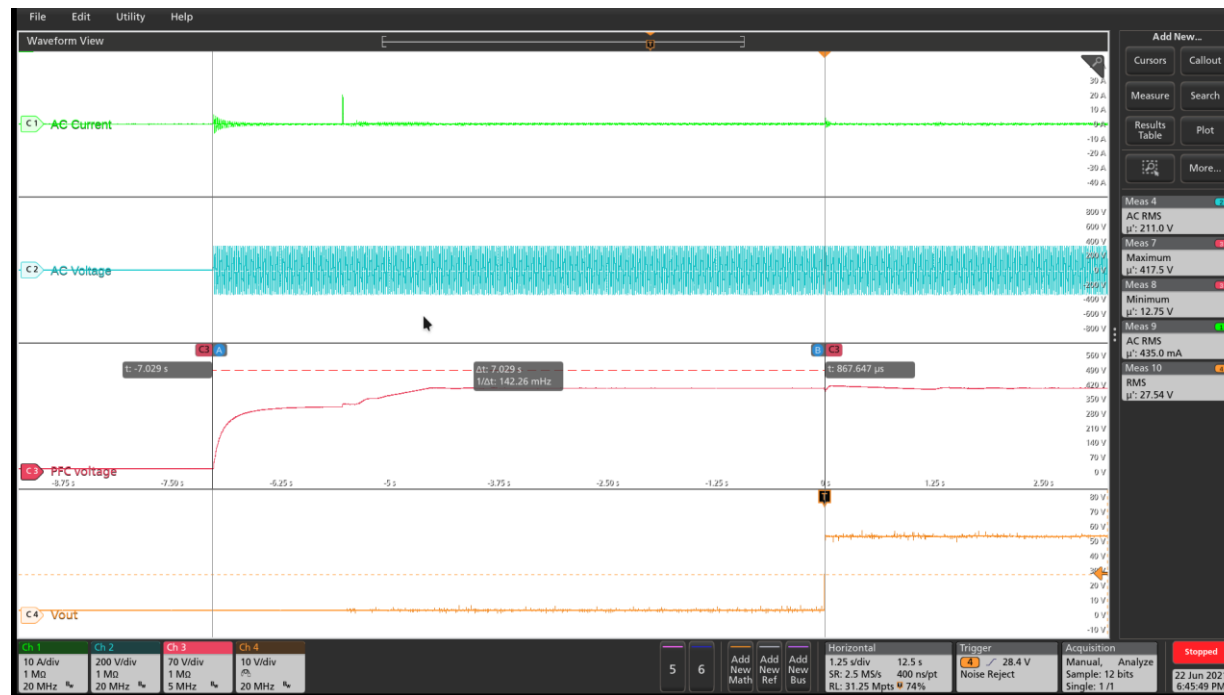
iTHD



Soft start 230Vac/50Hz

No load

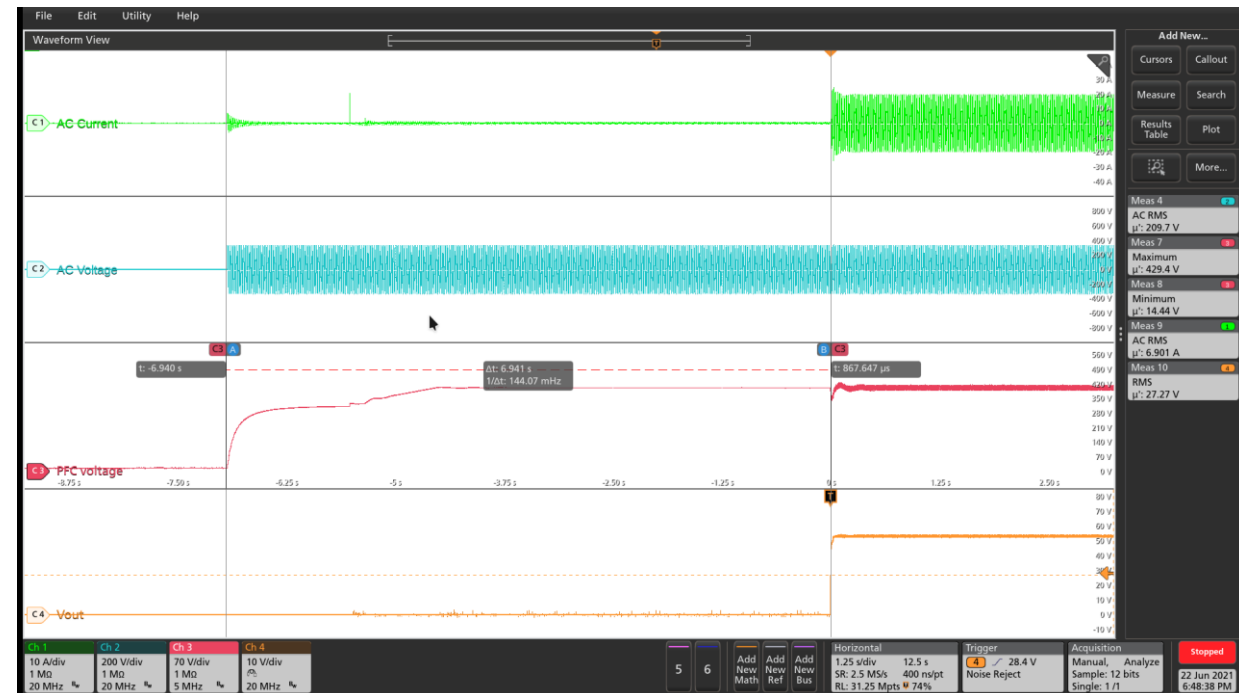
$T_{ss}=7.029s$



CH1: Input current (10A/div)
CH2: Input Voltage (200V/div)
CH3: Bulk Cap Voltage (70V/div)
CH4: Output Voltage (10V/div)

Full load

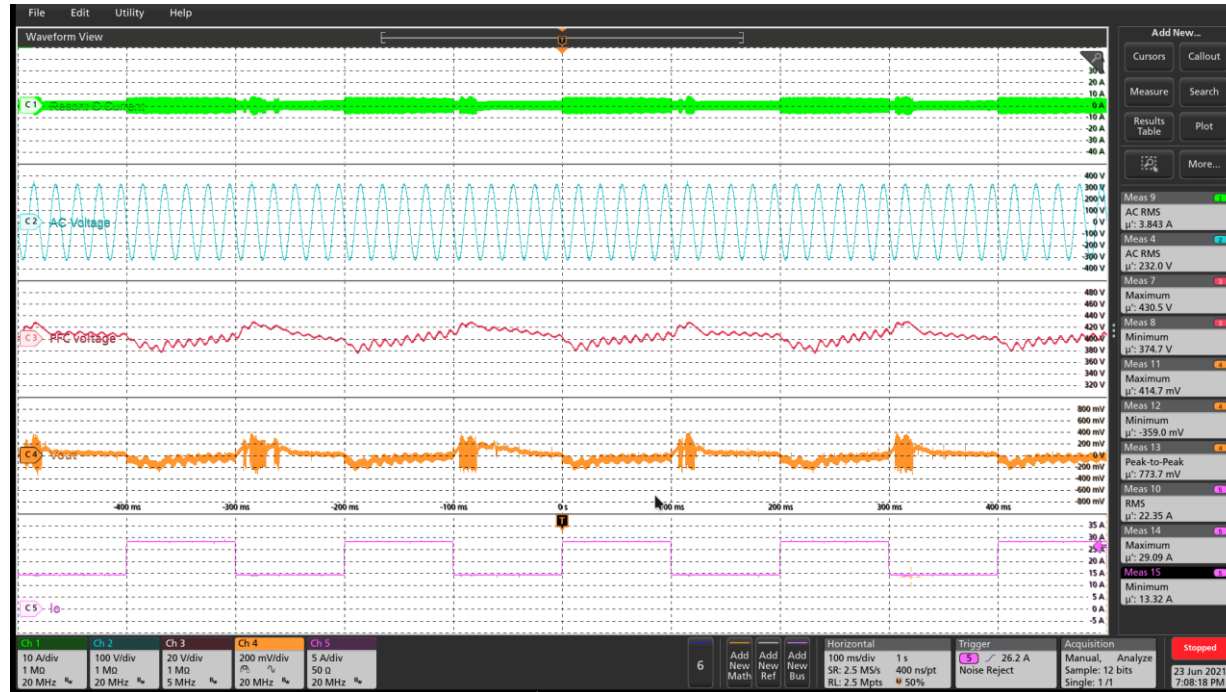
$T_{ss}=6.941s$



CH1: Input current (10A/div)
CH2: Input Voltage (200V/div)
CH3: Bulk Cap Voltage (70V/div)
CH4: Output Voltage (10V/div)

Load Transient response 230Vac/50Hz

25%~50%~25% 0.1A/us 100ms



CH1: Resonant current (10A/div)
CH2: Input Voltage (100V/div)
CH3: Bulk Cap Voltage (20V/div Vos=400V)
CH4: Output Voltage (200mV/div AC coupled)
CH5: Load Current (5A/div)

50%~75%~50% 0.1A/us 100ms

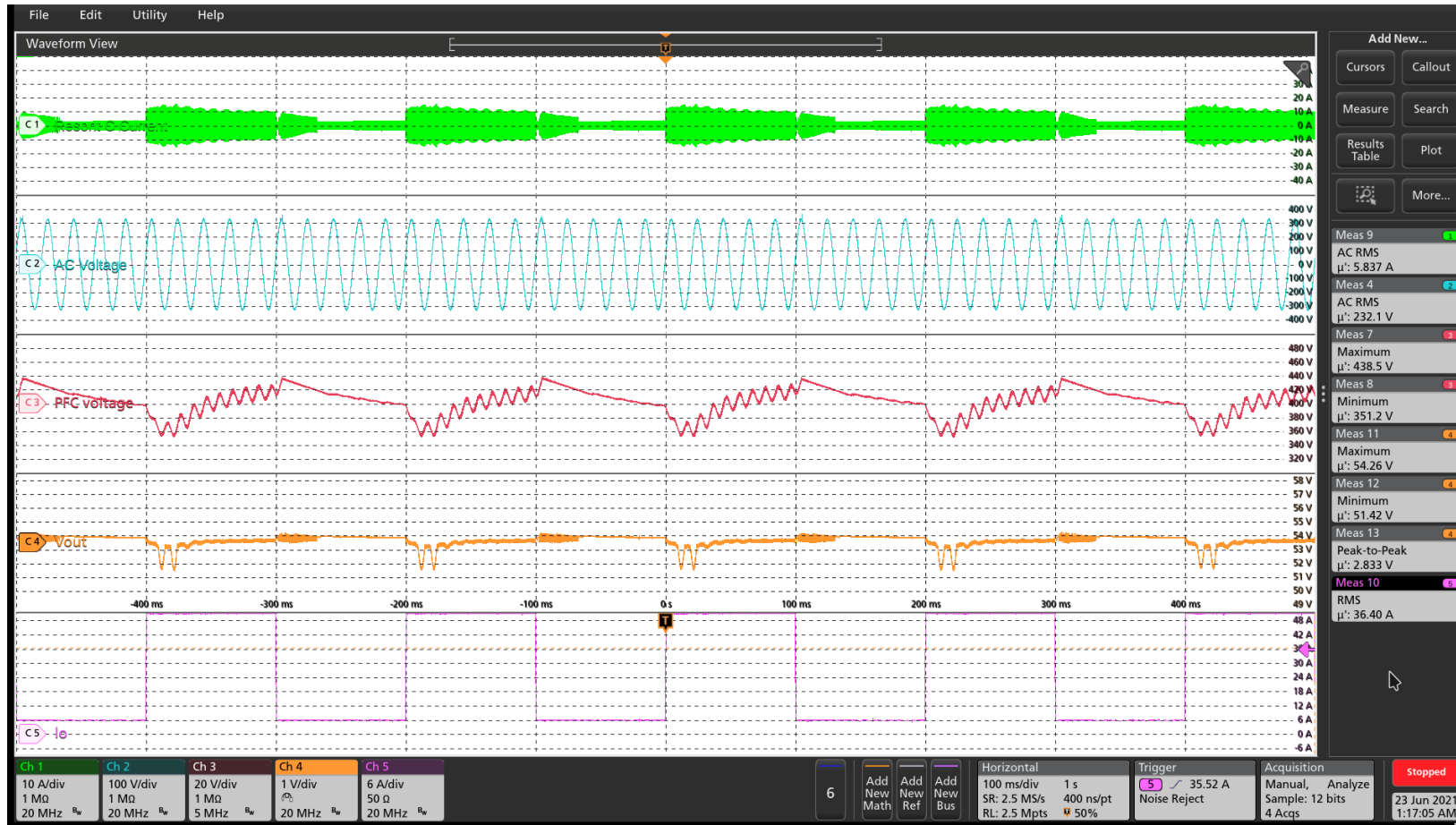


CH1: Resonant current (10A/div)
CH2: Input Voltage (100V/div)
CH3: Bulk Cap Voltage (20V/div Vos=400V)
CH4: Output Voltage (200mV/div AC coupled)
CH5: Load Current (8A/div)

Load Transient Response

230Vac/50Hz

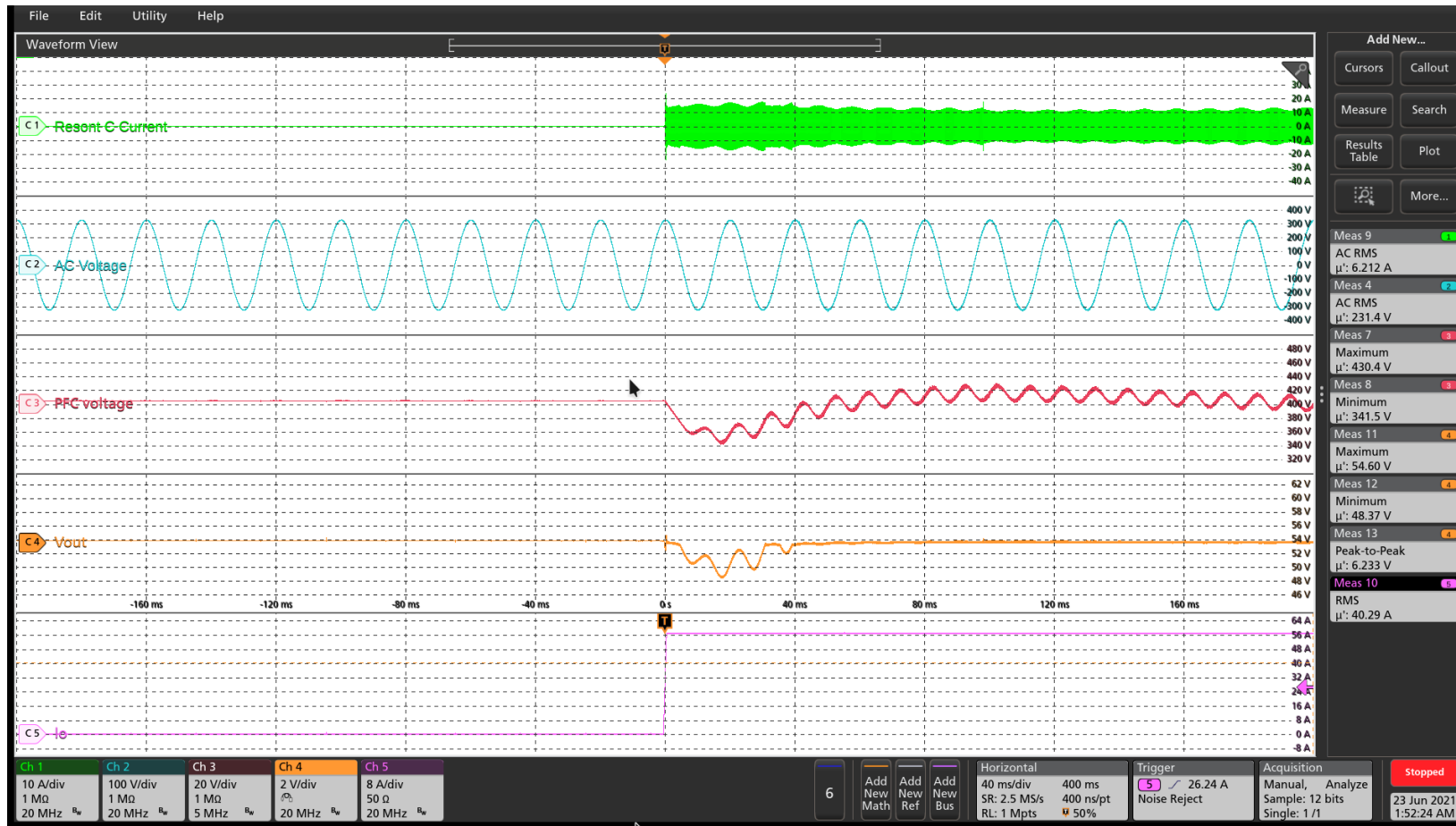
10%~90%~10% 0.1A/us 100ms



CH1: Resonant current (10A/div)
CH2: Input Voltage (100V/div)
CH3: Bulk Cap Voltage (20V/div Vos=400V)
CH4: Output Voltage (1V/div Vos=53.5V)
CH5: Load Current (6A/div)

Load on with full power 230Vac/50Hz

Load on with full power

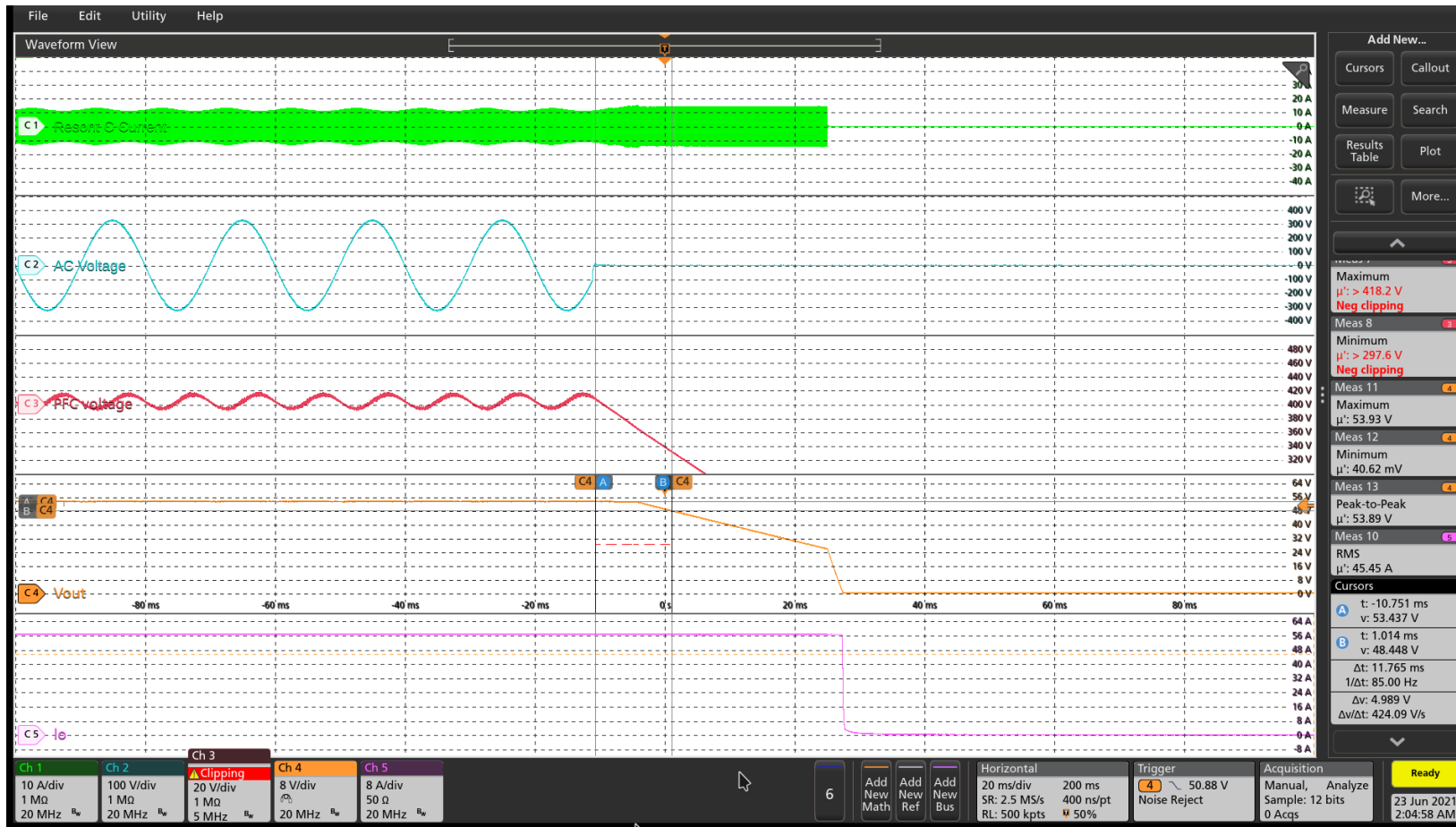


CH1: Resonant current (10A/div)
CH2: Input Voltage (100V/div)
CH3: Bulk Cap Voltage (20V/div Vos=400V)
CH4: Output Voltage (2V/div Vos=53.5V)
CH5: Load Current (8A/div)

Hold up time 230Vac/50Hz

Holdup time

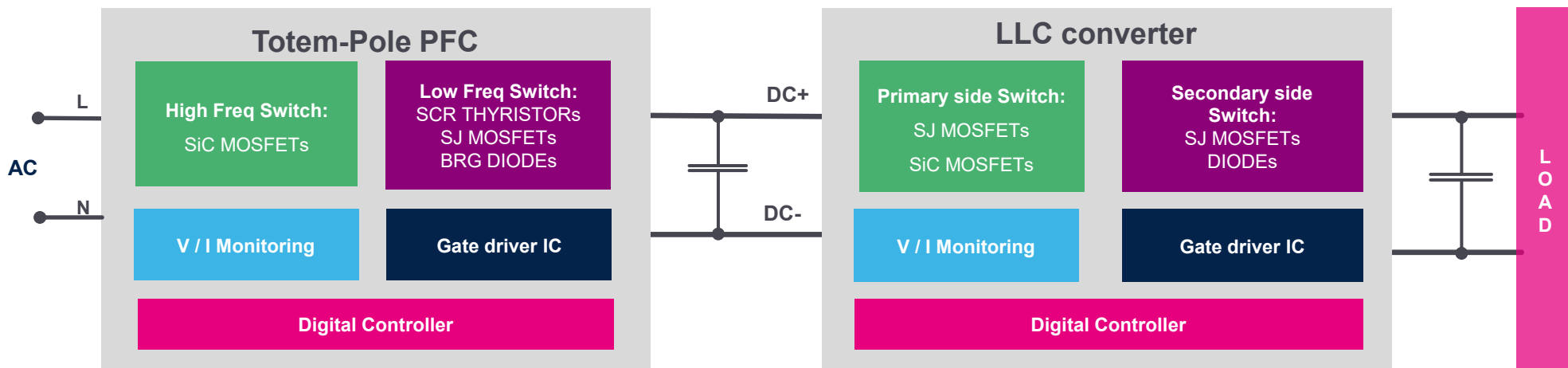
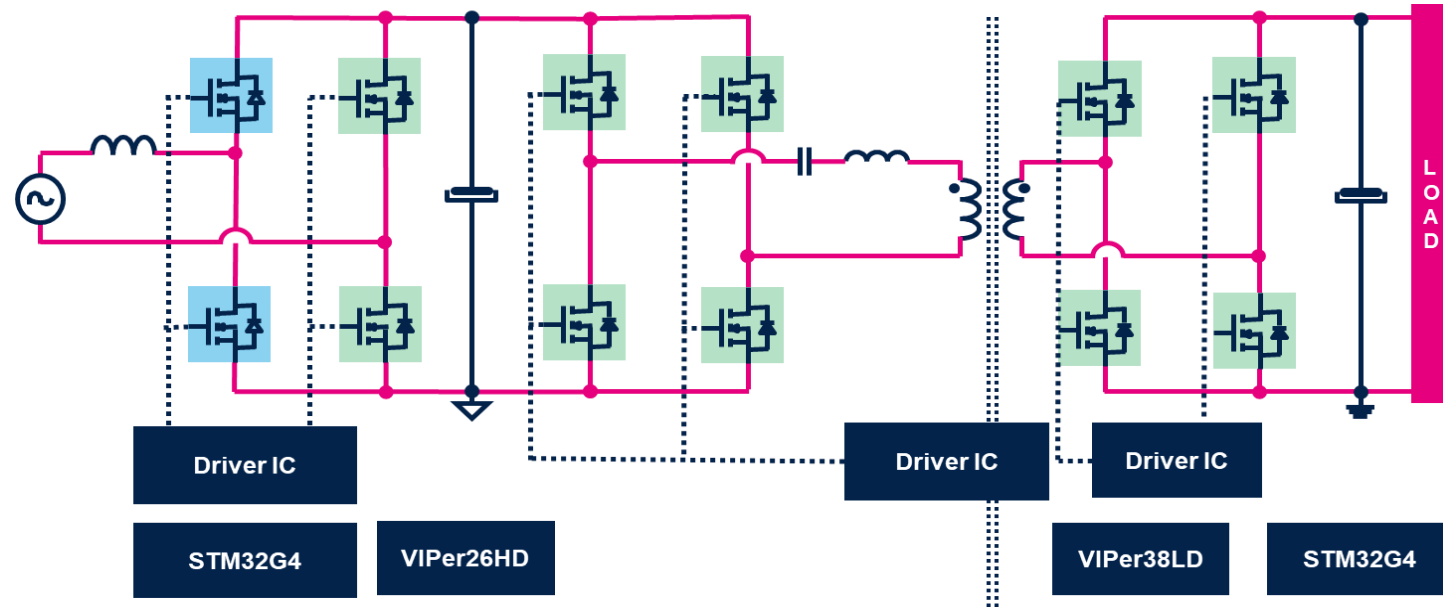
$T_{\text{holdup}} = 10.751 \text{ ms}$ From 53.5V drop to 48.5V



CH1: Resonant current (10A/div)
CH2: Input Voltage (100V/div)
CH3: Bulk Cap Voltage (20V/div Vos=400V)
CH4: Output Voltage (8V/div)
CH5: Load Current (8A/div)

ST Products introduction

ST products introduction



STPOWER SiC MOSFET

Product family ratings and applications

Breakdown Voltage

650 V

750/900 V

1200 V

1700 V

Series

Gen2

Gen3

Gen3

Gen1

Gen2

Gen3

Gen1

On-state resistance

18-55mΩ

14-55mΩ

11mΩ

52-520mΩ

21-75mΩ

15-70mΩ

65mΩ & 0.7Ω

Focus Applications

OBC & DC-DC
Renewable energy
Power Supply
Industrial drives

OBC & DC-DC
Power Supply
Solar
Telecom &
Server

DC-DC
Renewable
energy
Telecom &
Server

Photovoltaic
HVAC
Power supply

Inverter
Street Lighting
Charging
stations
Industrial

Inverter
DC-DC
Power Supply

DC-DC
Power Supply
Renewable
energy

SiC MOSFETs Gen2

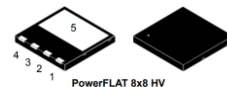
V _{gs} =18V	V _{DS} [V]	R _{DS(on)} Typ@ 25 °C [mΩ]	Id [A]	Package				
				HiP247	HiP247-LL	HiP247-4LL	H2PAK-7L	Power flat 8*8
Industrial Grade				Tj max= 200°C			Tj max= 175°C	Tj max= 175°C
SCTW90N65G2V	650	18	119	X				
SCTWA90N65G2V					X			
SCTWA90N65G2V-4						X		
SCTH90N65G2V-7							X	
SCTL90N65G2V								X
SCTW35N65G2V	650	55	45	X				
SCTWA35N65G2V					X			
SCTWA35N65G2V-4						X		
SCTH35N65G2V-7							X	
SCTL35N65G2V								X

KEY FEATURES

- Very low switching losses
- Low power losses at high temperatures
- Higher operating temperature (up to 200 °C)
- Body diode with no recovery losses
- Easy to drive

KEY BENEFITS

- Smaller form factor and higher power density
- Reduced size/cost of passive components
- Higher system efficiency
- Reduced cooling requirements and heatsink size



SiC MOSFETs Gen3

Automotive Grade AECQ 101 Compliant	V _{DS} [V]	R _{DS(on)} Typ @ 25°C [Ω], *V _{GS} =18V	Package	Status	Eng. samp
SCT055HU65G3AG	650	0.055	HU3PAK	Available	
SCT055H65G3AG			H2PAK-7L		Available
SCT055W65G3AG			HiP247		Available
SCT055W65G3-4AG			HiP247 4L (LL)		Available
SCT040HU65G3AG	650	0.042	HU3PAK	Available	
SCT040H65G3AG			H2PAK-7	Available	
SCT040H65G3SAG			H2PAK-7 Straight leed	Available	
SCT027HU65G3AG	650	0.027	HU3PAK		Available
SCT027H65G3AG			H2PAK-7L		Available
SCT027W65G3AG			HiP247		Available
SCT027W65G3-4AG			HiP247 4L (LL)		Available
SCT018HU65G3AG	650	0.021	HU3PAK		Available
SCT018H65G3AG			H2PAK-7L	Available	
SCT018W65G3AG			HiP247		Available
SCT018W65G3-4AG			HiP247 4L (LL)		Available
SCT014HU65G3AG	650	0.014	HU3PAK		Available

KEY FEATURES

- Very low switching losses
- Low power losses at high temperatures
- Higher operating temperature (up to 200 °C)
- Body diode with no recovery losses
- Easy to drive

KEY BENEFITS

- Smaller form factor and higher power density
- Reduced size/cost of passive components
- Higher system efficiency
- Reduced cooling requirements and heatsink size

High voltage MOSFET series super-junction MDmesh™

Breakdown Voltage

600V	650V	700V	800V – 1700V
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MDmesh series

M2	M6	DM2	DM6	M5	DM2	DM6	M6	K5
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Focus Topology

Flyback, PFC/LLC resonant conv.	Flyback, PFC/LLC high efficiency	HB / FB, ZVS, LLC	HB / FB, ZVS, LLC high efficiency	Hi-end-power PFC and hard switching topologies	HB / FB, ZVS, LLC high power level	HB / FB, ZVS, LLC high power level high efficiency	Flyback topology
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Focus Applications

Charger adapters Led lighting, Medical	Server, 5G, Consumer, Adapters, Solar, Medical	Solar, Server, Telecom SMPS, EV-Car/Charging, Medical	LED driver, LED lighting, auxiliary SMPS, EV-Car, Medical
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SJ MOSFETs

600V DM6 series

Part Number	Vds (V)	RDS(on)@typ 25	Id(A)	Package									
				TO-247	TO247-4	TO-247 long leads	TO-LL	TO-220	D2PAK	HU3PAK	H2PAK-2	I2PAK	PowerFLAT 8x8 HV
STW75N60DM6	600	0.036	72	X									
STWA75N60DM6						X							
STW72N60DM6AG	600	0.042	56	X									
STW70N60DM6-4			62		X								
STWA70N60DM6						X							
STW70N60DM6				X									
STWA67N60DM6	600	0.054	58			X							
STO67N60DM6		0.059					X						
STWA65N60DM6	600	0.071	46			X							
STW65N60DM6				X									
STO65N60DM6		0.076					X						
STW52N60DM6	600	0.074	45	X									
STP50N60DM6	600	0.08	36					X					
STB47N60DM6AG	600	0.08	36						X				
STH47N60DM6-2AG											X		
STI47N60DM6AG												X	
STHU47N60DM6AG										X			
STL52N60DM6	600	0.084	45										X

SJ MOSFETs

650V DM6 series

Part Number	Vds (V)	RDS(on)@typ 25	Id(A)	Package						
				TO-247	TO247-4	TO-247 long leads	TO-LL	TO-220	D2PAK	HU3PAK
STW75N65DM6-4	650	0.036	75		X					
STWA75N65DM6						X				
STWA68N65DM6AG	650	0.039	72			X				
STW68N65DM6-4AG					X					
STW70N65DM6	650	0.04	68	X						
STWA70N65DM6						X				
STW70N65DM6-4					X					
STW68N65DM6	650	0.059	55	X						
STWA68N65DM6						X				
STO68N65DM6		0.065					X			
STWA46N65DM6AG	650	0.063	50			X				
STWA38N65DM6AG	650	0.082	42			X				
STP50N65DM6	650	0.091	33					X		
STB50N65DM6									X	
STW50N65DM6				X						
STWA32N65DM6AG	650	0.097	37			X				
STHU32N65DM6AG										X



Isolated gate drive for SiC MOSFET

1700 V Galvanic isolated Single & Dual channel



SO-8

STGAP2S
STGAP2SC
STGAP2SiCSN
STGAP2SiCSNC



SO-16

STGAP2D

Galvanic isolated, up to
1700 V high voltage rail

Extreme Transient
Immunity up to
 $\pm 100 \text{ V / ns}$



Fast Switching
Frequency
(Tp 80ns only)

High current capability
4A Isink / Isource

6000 V Galvanic isolated Single & Dual channel



SO-8W

STGAP2HS
STGAP2HSC
STGAP2SiCS
STGAP2SiCSC



SO-36W

STGAP2HD
STGAP2SiCD

Galvanic isolated, up to
6000 V high voltage rail

Extreme Transient
Immunity up to
 $\pm 100 \text{ V / ns}$



Fast Switching
Frequency
(Tp 80ns only)

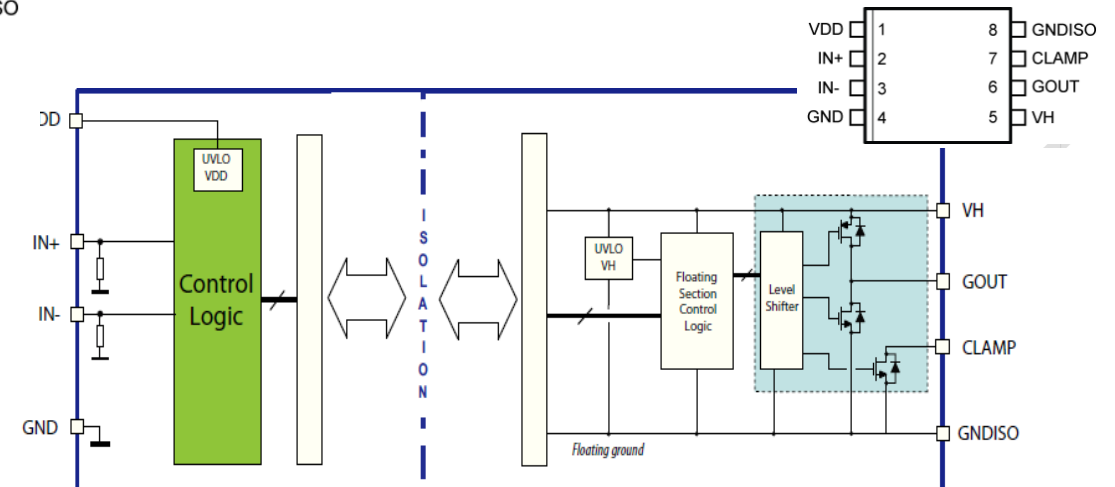
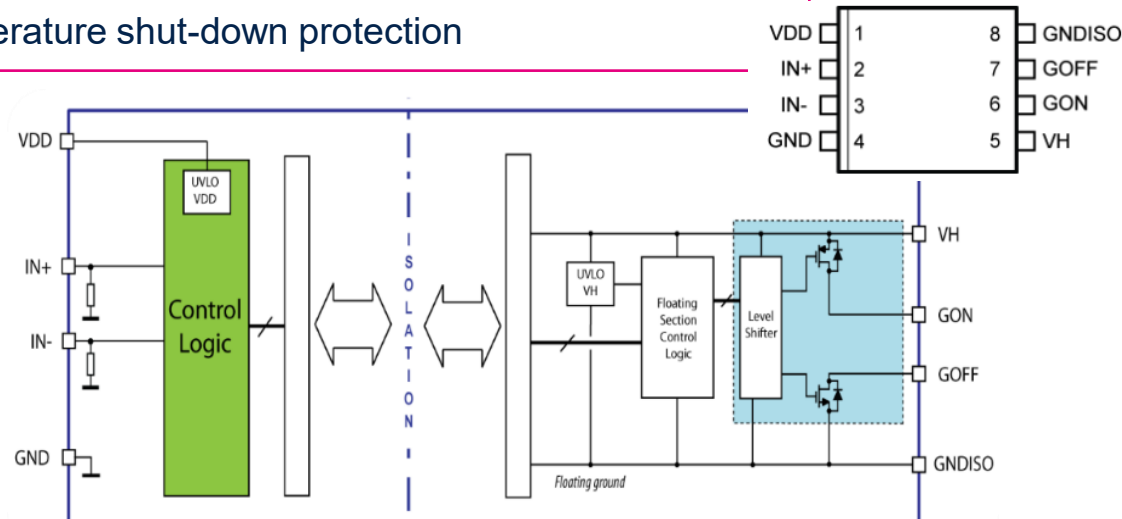
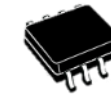
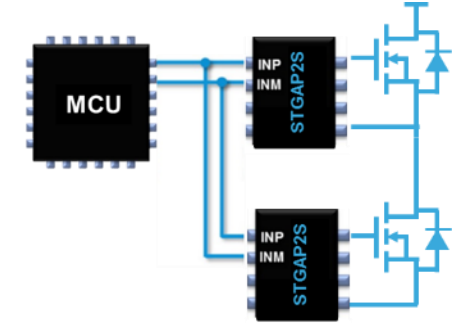
High current capability
4A Isink / Isource

STGAP2S, STGAP2SC STGAP2SICSN, STGAP2SICSNC

1700 V, 4A isolated gate drivers

- 3V3/ 5 V logic inputs (logic thresholds 1/3, 2/3 of VDD)
- **Up to 26 V supply voltage**
- **4 A Sink/Source current capability**
- Short propagation delay: 80 ns
- UVLO Function
- Stand-by function
- 100 V/ns CMTI
- High voltage rail up to 1700 V
- Temperature shut-down protection

- Active High & Active Low input pins, for HW interlocking
- **STGAP2S/STGAP2SICSN:**
- Separated Outputs option for easy gate driving tuning
- **STGAP2SC/STGAP2SICSNC:**
- Miller CLAMP pin option to avoid induced turn-on
- Negative gate drive ability
- SO8 Package

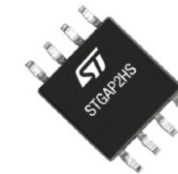
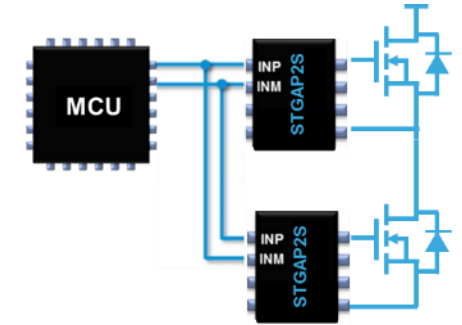


STGAP2HS, STGAP2HSC STGAP2SiCS, STGAP2SiCSC

6kV, 4A isolated gate drivers

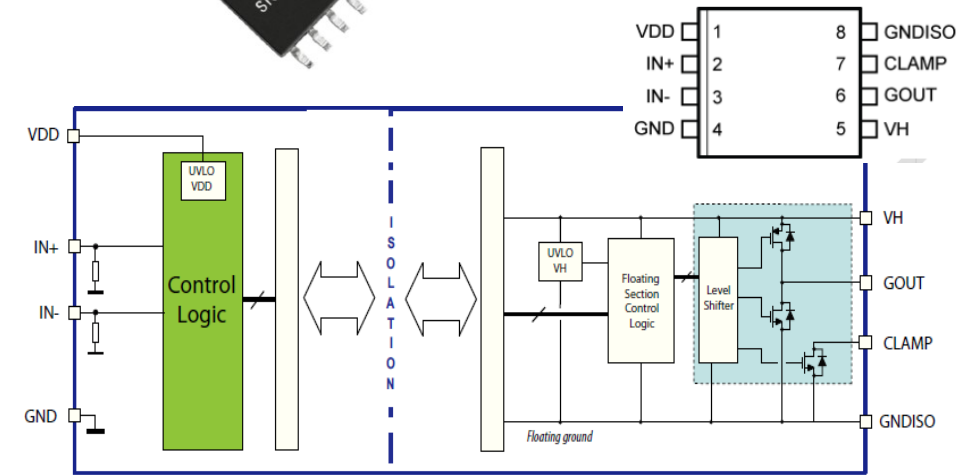
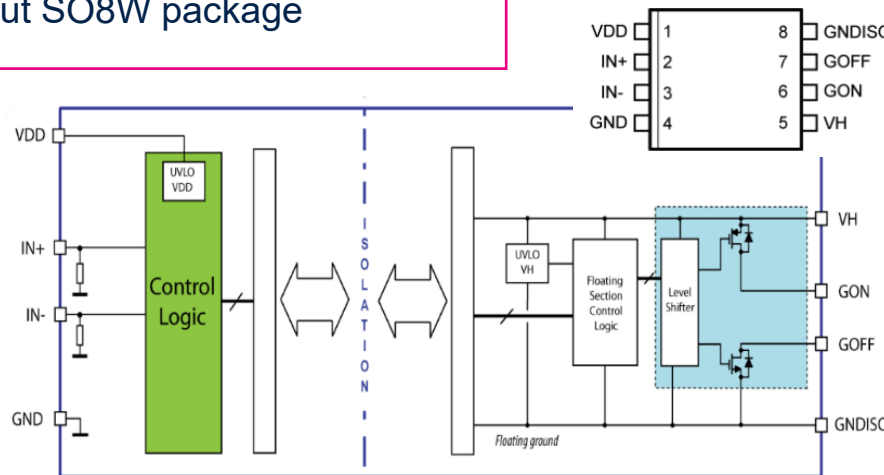
- 3.3V/5V logic inputs (logic thresholds 1/3, 2/3 of VDD)
- **Up to 26 V supply voltage**
- **4 A Sink/Source current capability**
- Short propagation delay: 80 ns
- **UVLO Function (optimized for SiC Version)**
- Stand-by function
- 100 V/ns CMTI
- Galvanic isolated up to 6kV
- Temperature shut-down protection
- Compact and simplified layout SO8W package

- Active High & Active Low input pins, for HW interlocking
- **STGAP2HS/STGAP2SICS:**
- Separated Outputs option for easy gate driving tuning
- **STGAP2HSC/STGAP2SiCSC:**
- Miller CLAMP pin option to avoid induced turn-on
- Negative gate drive ability
- SO8-W Package



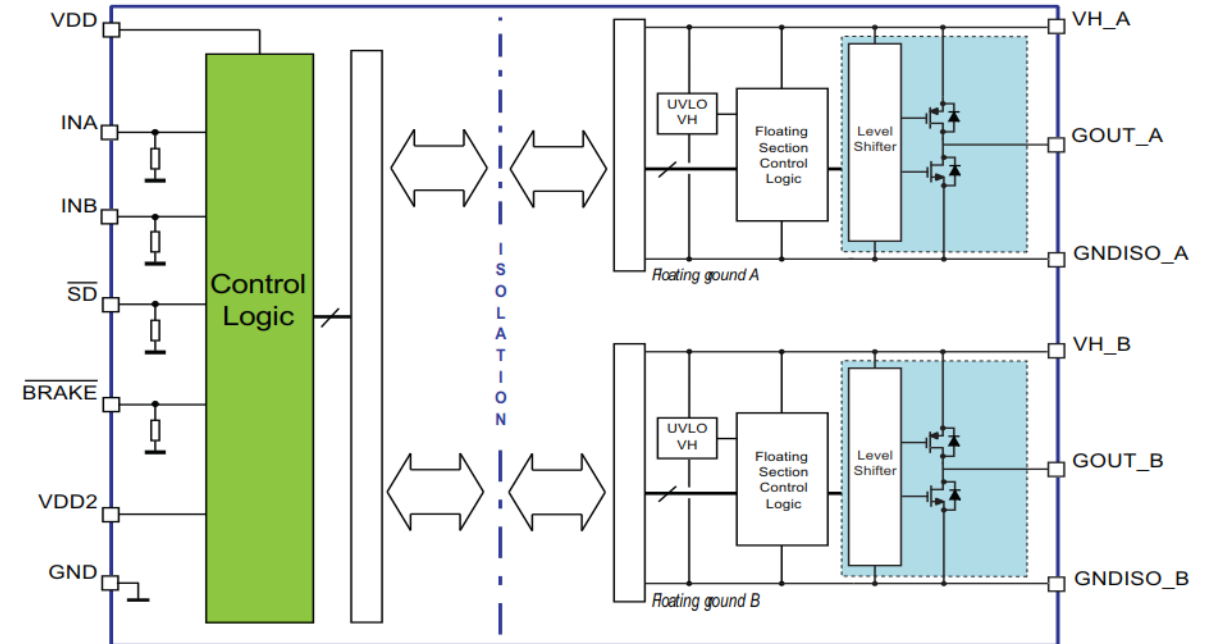
KEY APPLICATIONS

- Motor control
- Factory automation
- Industrial drives and Fans
- DC/ DC converters
- Welding



1700 V, 4A isolated gate drivers

- 3.3V/5V logic inputs (logic thresholds 1/3, 2/3 of VDD)
- **Up to 26 V supply voltage**
- **4 A Sink/Source current capability**
- Short propagation delay: 80 ns
- UVLO Function
- Stand-by function
- 100 V/ns CMTI
- High voltage rail up to 1700 V
- Temperature shut-down protection
- Single input pin, in phase with output
- Shut-Down SD pin, with integrated pull-down
- BRAKE pin
- Interlocking
- Negative gate drive ability
- SO16 Package



KEY APPLICATIONS

- Motor control
- Factory automation
- Industrial drives and fans
- DC-DC converters
- Induction heating
- Welding

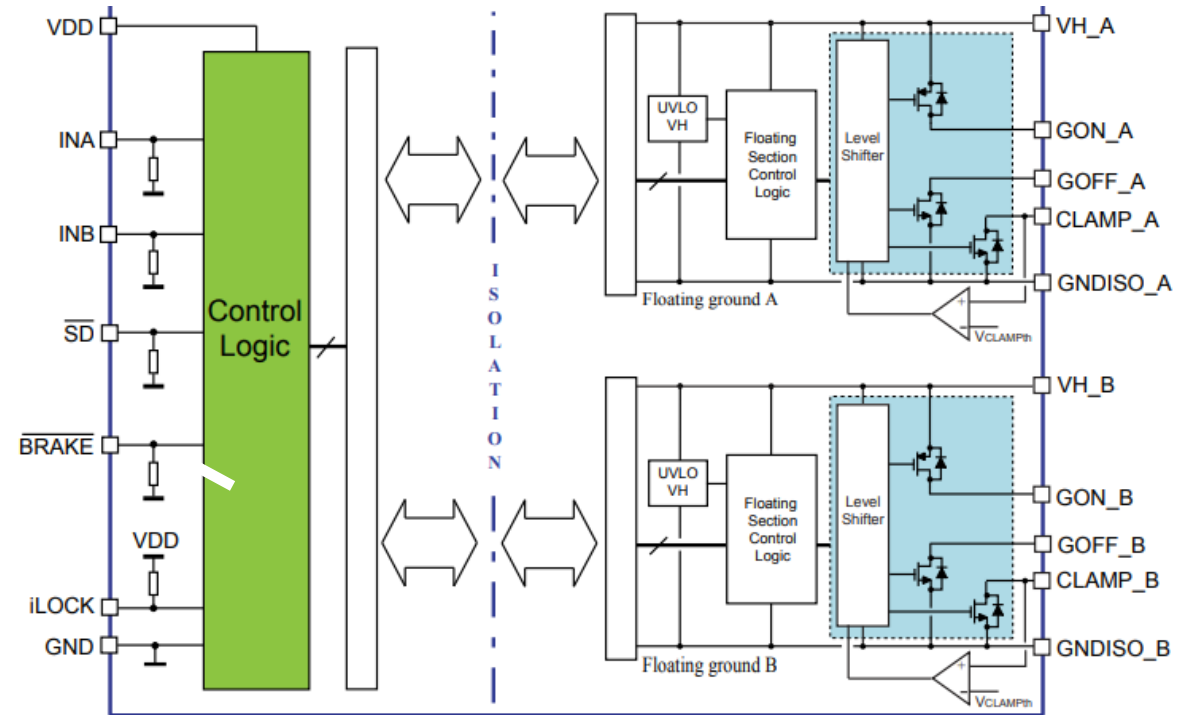


VDD	1	16	GNDISO_A
INA	2	15	GOUT_A
INB	3	14	VH_A
SD	4	13	N.C.
BRAKE	5	12	N.C.
VDD2	6	11	GNDISO_B
GND	7	10	GOUT_B
N.C.	8	9	VH_B

STGAP2HD, STGAP2SICD

6kV, 4A isolated gate drivers

- High voltage rail up to 1200 V
- Driver current capability: 4 A sink/source
- dV/dt transient immunity ± 100 V/ns
- Overall input-output propagation delay: 75 ns
- Separate sink and source option for easy gate driving configuration
- 4 A Miller CLAMP
- UVLO function
- Configurable interlocking function
- Dedicated SD and BRAKE pins
- Gate driving voltage up to 26 V
- 3.3 V, 5 V TTL/CMOS inputs with hysteresis
- Temperature shutdown protection
- Standby function
- 6 kV galvanic isolation
- Wide Body SO-36W



KEY APPLICATIONS

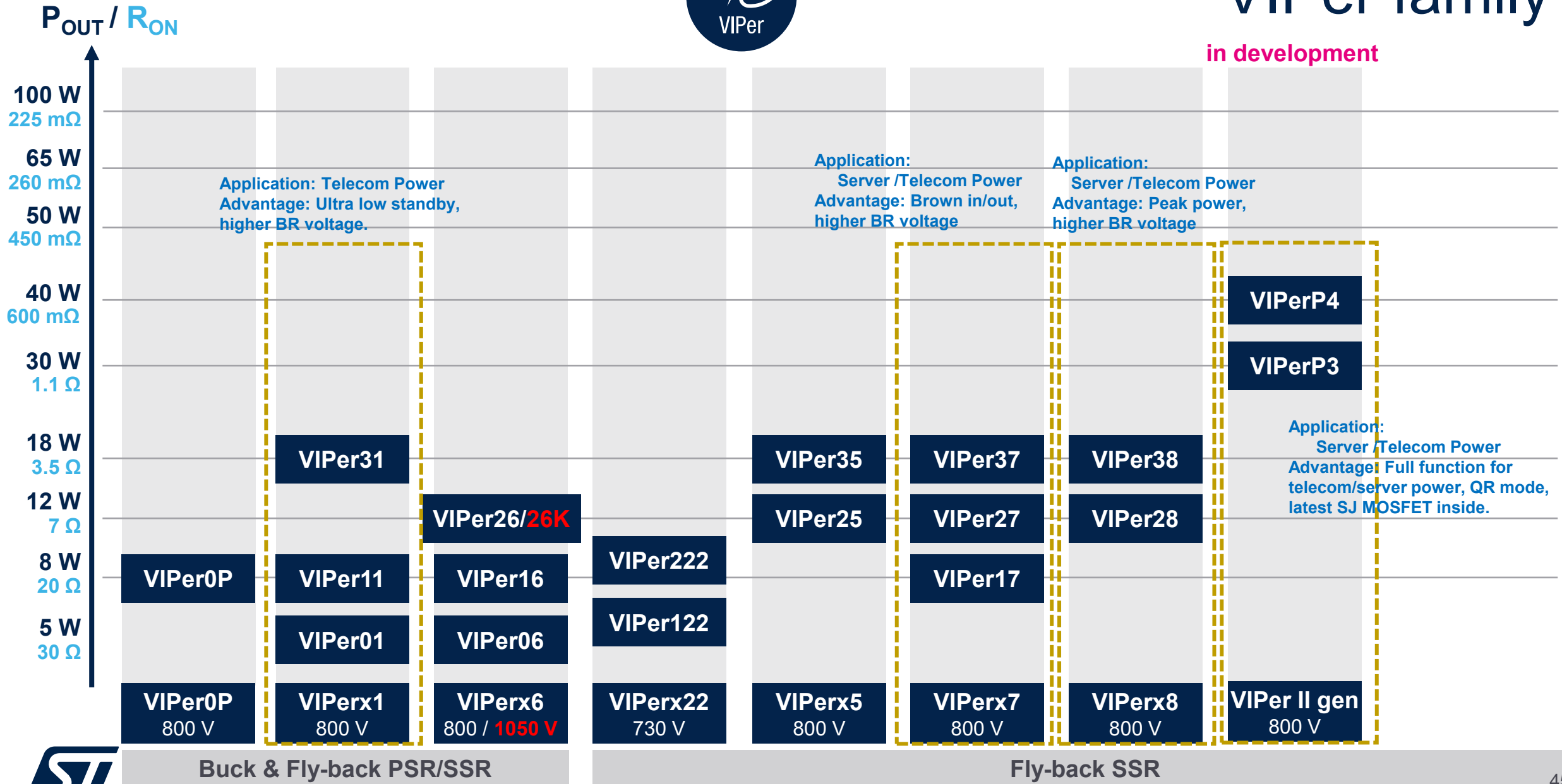
- Battery chargers
- Induction heating
- PFC converters
- DC-DC converters
- Inverter
- Welding
- Power supply units
- UPS

N.C.	1	36	N.C.
N.C.	2	35	GNDISO_A
N.C.	3	34	GNDISO_A
N.C.	4	33	CLAMP_A
N.C.	5	32	GOFF_A
VDD	6	31	GON_A
INA	7	30	VH_A
INB	8		
SD	9		
BRAKE	10		
ILOCK	11		
N.C.	12	25	CLAMP_B
GND	13	24	GNDISO_B
N.C.	14	23	GOFF_B
N.C.	15	22	GON_B
N.C.	16	21	N.C.
N.C.	17	20	VH_B
N.C.	18	19	N.C.





VIPer family



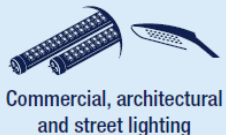
STM32G474 MCU

The STM32G474 based on a 32-bit Arm® Cortex®-M4 core with FPU and DSP instructions running at 170 MHz is well suited for digital power conversion

Hi-resolution PWM and Rich Analog STM32G474 MCU for Digital Control

- 170MHz 32-bit Arm® Cortex®-M4 core with FPU
- Routine booster of CCM-SRAM up to 32 kb
- Mathematic hardware accelerators (CORDIC / FMAC)
- High resolution timer (184ps) for precise PWM control
- Rich advanced analog
- USB type-C Power Delivery (PD)
- +/- 1% internal clock

MAIN APPLICATIONS



Commercial, architectural and street lighting



Server/Telecom



Welding



Charging station



UPS & Data center Power supply



Solar inverters



Connectivity

4x SPI, 4x I²C, 6x UART

1x USB 2.0 FS,
1x USB-C PD3.0 (+PHY)

3x CAN-FD

2x I²S half duplex, SAI

External interface

FSMC 8-/16-bit (TFT-LCD,
SRAM, NOR, NAND)

Quad SPI

Accelerators

ART Accelerator™

32-Kbyte CCM-SRAM

Math Accelerators

Cordic (trigo...)
Filtering

Arm® Cortex®-M4
Up to 170 MHz
213 DMIPS

Floating Point Unit

Memory Protection Unit

Embedded Trace
Macrocell

16-channel DMA + MUX

Up to 2x 256-Kbyte
Flash memory / ECC
Dual Bank

96-Kbyte SRAM

Timers

5x 16-bit timers

2x 16-bit basic timers

3x 16-bit advanced
motor control timers

2x 32-bit timers

1x 16-bit LP timer

1x HR timer (D-Power)
12-channel w/ 184ps
(A. delay line)

Analog

5x 12-bit ADC w/ HW overspl

7x Comparators

7x DAC (3x buff + 4x non-buff)

6x Op-Amp (PGA)

1x temperature sensor

Internal voltage reference

Summary

Summary

- This digital solution with **STM32G4** will help you achieve **high efficiency / high power density** for 5G telecom power supply
- ST provides the latest technologies (SiC/STGAP/M6/STM32) for high power density and high efficiency solutions on 5G telecom power applications.
- This reference design offers:
 - Digital power solution for totem-pole PFC converter and Full-bridge LLC with synchronous rectifiers
 - Peak efficiency is greater than 96.5%, PFC section is 98.5%, DCDC section is 98.2%
 - iTHD distortion lower than 5% when load is greater than 50%
 - Inrush-current limitation is based on PTC resistor and relay-controlled.
 - Adaptive duty change for turn-off control bases on the comparison of sampled V_{ds} and V_{TH_SR} threshold.



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Power & SPIN Microsite



Our technology starts with You



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